

# microID<sup>TM</sup> 13.56 MHz RFID System Design Guide

**INCLUDES:** 

- Passive RFID Basics Application Note
- MCRF355/360 Data Sheet
- Microchip Development Kit Sample Format
- MCRF355/360 Factory Programming Support (SQTP<sup>SM</sup>)
- MCRF355/360 Applications Application Note
- Antenna Circuit Design Application Note
- 13.56 MHz Reader Reference Design
- Contact Programmer Reference Design

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# **Passive RFID Basics**

Author: Pete Sorrells Microchip Technology Inc.

# INTRODUCTION

Radio Frequency Identification (RFID) systems use radio frequency to identify, locate and track people, assets, and animals. Passive RFID systems are composed of three components - an interrogator (reader), a passive tag, and a host computer. The tag is composed of an antenna coil and a silicon chip that includes basic modulation circuitry and non-volatile memory. The tag is energized by a time-varying electromagnetic radio frequency (RF) wave that is transmitted by the reader. This RF signal is called a carrier signal. When the RF field passes through an antenna coil, there is an AC voltage generated across the coil. This voltage is rectified to supply power to the tag. The information stored in the tag is transmitted back to the reader. This is often called backscattering. By detecting the backscattering signal, the information stored in the tag can be fully identified.

# DEFINITIONS

# Reader

Usually a microcontroller-based unit with a wound output coil, peak detector hardware, comparators, and firmware designed to transmit energy to a tag and read information back from it by detecting the backscatter modulation.

# Tag

An RFID device incorporating a silicon memory chip (usually with on-board rectification bridge and other RF front-end devices), a wound or printed input/output coil, and (at lower frequencies) a tuning capacitor.

# Carrier

A Radio Frequency (RF) sine wave generated by the reader to transmit energy to the tag and retrieve data from the tag. In these examples the ISO frequencies of 125 kHz and 13.56 MHz are assumed; higher frequencies are used for RFID tagging, but the communication methods are somewhat different. 2.45 GHz, for example, uses a true RF link. 125 kHz and 13.56 MHz, utilize transformer-type electromagnetic coupling.

# Modulation

Periodic fluctuations in the amplitude of the carrier used to transmit data back from the tag to the reader.

Systems incorporating passive RFID tags operate in ways that may seem unusual to anyone who already understands RF or microwave systems. There is only one transmitter – the passive tag is not a transmitter or transponder in the purest definition of the term, yet bidirectional communication is taking place. The RF field generated by a tag reader (the energy transmitter) has three purposes:

- 1. Induce enough power into the tag coil to energize the tag. Passive tags have no battery or other power source; they must derive all power for operation from the reader field. 125 kHz and 13.56 MHz tag designs must operate over a vast dynamic range of carrier input, from the very near field (in the range of 200 VPP) to the maximum read distance (in the range of 5 VPP).
- Provide a synchronized clock source to the tag. Many RFID tags divide the carrier frequency down to generate an on-board clock for state machines, counters, etc., and to derive the data transmission bit rate for data returned to the reader. Some tags, however, employ onboard oscillators for clock generation.
- 3. Act as a carrier for return data from the tag. Backscatter modulation requires the reader to peak-detect the tag's modulation of the reader's own carrier. See page 2 for additional information on backscatter modulation.

# SYSTEM HANDSHAKE

Typical handshake of a tag and reader is as follows:

- The reader continuously generates an RF carrier sine wave, watching always for modulation to occur. Detected modulation of the field would indicate the presence of a tag.
- 2. A tag enters the RF field generated by the reader. Once the tag has received sufficient energy to operate correctly, it divides down the carrier and begins clocking its data to an output transistor, which is normally connected across the coil inputs.
- 3. The tag's output transistor shunts the coil, sequentially corresponding to the data which is being clocked out of the memory array.
- 4. Shunting the coil causes a momentary fluctuation (dampening) of the carrier wave, which is seen as a slight change in amplitude of the carrier.
- 5. The reader peak-detects the amplitude-modulated data and processes the resulting bitstream according to the encoding and data modulation methods used.

# **BACKSCATTER MODULATION**

This terminology refers to the communication method used by a passive RFID tag to send data back to the reader. By repeatedly shunting the tag coil through a transistor, the tag can cause slight fluctuations in the reader's RF carrier amplitude. The RF link behaves essentially as a transformer; as the secondary winding (tag coil) is momentarily shunted, the primary winding (reader coil) experiences a momentary voltage drop. The reader must peak-detect this data at about 60 dB down (about 100 mV riding on a 100V sine wave) as shown in Figure 1.

This amplitude-modulation loading of the reader's transmitted field provides a communication path back to the reader. The data bits can then be encoded or further modulated in a number of ways.

# FIGURE 1: AMPLITUDE – MODULATED BACKSCATTERING SIGNAL



# DATA ENCODING

Data encoding refers to processing or altering the data bitstream in-between the time it is retrieved from the RFID chip's data array and its transmission back to the reader. The various encoding algorithms affect error recovery, cost of implementation, bandwidth, synchronization capability, and other aspects of the system design. Entire textbooks are written on the subject, but there are several popular methods used in RFID tagging today:

- 1. **NRZ (Non-Return to Zero) Direct.** In this method no data encoding is done at all; the 1's and 0's are clocked from the data array directly to the output transistor. A low in the peak-detected modulation is a '0' and a high is a '1'.
- 2. Differential Biphase. Several different forms of differential biphase are used, but in general the bitstream being clocked out of the data array is modified so that a transition always occurs on every clock edge, and 1's and 0's are distinguished by the transitions within the middle of the clock period. This method is used to embed clocking information to help synchronize the reader to the bitstream; and because it always has a transition at a clock edge, it inherently provides some error correction capability. Any clock edge that does not contain a transition in the data stream is in error and can be used to reconstruct the data.
- 3. **Biphase\_L (Manchester).** This is a variation of biphase encoding in which there is not always a transition at the clock edge.



# FIGURE 2: VARIOUS DATA CODING WAVEFORMS

# DATA MODULATION

Although all the data is transferred to the host by amplitude-modulating the carrier (backscatter modulation), the actual modulation of 1's and 0's is accomplished with three additional modulation methods:

- Direct. In direct modulation, the Amplitude Modulation of the backscatter approach is the only modulation used. A high in the envelope is a '1' and a low is a '0'. Direct modulation can provide a high data rate but low noise immunity.
- FSK (Frequency Shift Keying). This form of modulation uses two different frequencies for data transfer; the most common FSK mode is Fc/8/10. In other words, a '0' is transmitted as an amplitude-modulated clock cycle with period corresponding to the carrier frequency divided by 8, and a '1' is transmitted as an amplitude-modulated clock cycle period corresponding to the carrier frequency divided by 10. The amplitude modulation of the carrier thus switches from Fc/8 to Fc/10 corresponding to 0's

and 1's in the bitstream, and the reader has only to count cycles between the peak-detected clock edges to decode the data. FSK allows for a simple reader design, provides very strong noise immunity, but suffers from a lower data rate than some other forms of data modulation. In Figure 3, FSK data modulation is used with NRZ encoding.

- 3. **PSK (Phase Shift Keying).** This method of data modulation is similar to FSK, except only one frequency is used, and the shift between 1's and 0's is accomplished by shifting the phase of the backscatter clock by 180 degrees. Two common types of PSK are:
  - Change phase at any '0', or
  - Change phase at any data change (0 to 1 or 1 to 0).

PSK provides fairly good noise immunity, a moderately simple reader design, and a faster data rate than FSK. Typical applications utilize a backscatter clock of Fc/2, as shown in Figure 4.



# FIGURE 4: PSK MODULATED SIGNAL



# ANTICOLLISION

In many existing applications, a single-read RFID tag is sufficient and even necessary: animal tagging and access control are examples. However, in a growing number of new applications, the simultaneous reading of several tags in the same RF field is absolutely critical: library books, airline baggage, garment, and retail applications are a few.

In order to read multiple tags simultaneously, the tag and reader must be designed to detect the condition that more than one tag is active. Otherwise, the tags will all backscatter the carrier at the same time, and the amplitude-modulated waveforms shown in Figures 3 and 4 would be garbled. This is referred to as a *collision*. No data would be transferred to the reader. The tag/reader interface is similar to a serial bus, even though the "bus" travels through the air. In a wired serial bus application, arbitration is necessary to prevent bus contention. The RFID interface also requires arbitration so that only one tag transmits data over the "bus" at one time.

A number of different methods are in use and in development today for preventing collisions; most are patented or patent pending, but all are related to making sure that only one tag "talks" (backscatters) at any one time. See the *MCRF355/360 Data Sheet* (page 7) and the *13.56 MHz Reader Reference Design* (page 47) chapters for more information regarding the MCRF355/360 anticollision protocol.

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NOTES:

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# MCRF355/360

# **13.56 MHz Passive RFID Device with Anticollision**

# FEATURES

- Frequency of operation: 13.56 MHz
- Built-in anticollision algorithm for reading up to 50 tags in the same RF field
- "Cloaking" feature minimizes the detuning effects of adjacent tags
- Manchester coding protocol
- Data modulation frequency: 70 kHz
- 154 bits of user-programmable memory
- Contact programming or factory-programmed options
- Very low power CMOS design
- Die, wafer, PDIP or SOIC package options
- On-chip 100 pF resonance capacitor (MCRF360)
- · Read-only device after programming

# APPLICATION



# PACKAGE TYPE



# DESCRIPTION

The MCRF355 and MCRF360 are Microchip's newest additions to the microID<sup>™</sup> family of RFID tagging devices. They are uniquely designed read-only passive Radio Frequency Identification (RFID) devices with an advanced anticollision feature, operating at 13.56 MHz. The device is powered remotely by rectifying RF magnetic fields that are transmitted from an interrogator (reader).

The device has a total of six pads (see Die Layout). Three are used to connect the external resonant circuit elements. The additional three pads are used for programming and testing of the device. The device needs two external antenna coils (L1 and L2) to pick up the RF magnetic fields and also to send back encoded (modulated) data to the reader. The two antenna coils are connected in series. The first coil (L1) is connected between Antenna Pad A and Antenna Pad B. The second coil (L2) is connected between Antenna Pad B and Vss. The MCRF355 requires an external capacitor to form a resonant circuit along with the antenna coils. See Figure 6-2 for details.

The MCRF360 has 100 pF of internal resonance capacitor between Antenna Pad A and Vss (across the coils). This capacitance can be utilized to form a tuned LC circuit along with the external antenna coils. See Section 6.2 for external resonant circuits.

The device includes a modulation transistor that is located between Antenna Pad B and Vss. This modulation gate is used to send data to the reader. The modulation transistor is designed to result in approximately  $3\Omega$  of resistance between Drain, which is connected to Antenna Pad B, and Source, which is connected to Vss, when it is turned-on.

The LC circuit is tuned to the operating frequency (13.56 MHz) of the reader when the modulation transistor is in a turned-off condition. This condition is called *uncloaking*.

As the modulation transistor turns on, there will be a shorting effect across L2 due to the  $3\Omega$  resistance across it. This results in a change of the inductance of the antenna coil, and, therefore, the circuit no longer resonates at 13.56 MHz. This condition is called *cloaking*.

The occurrence of the cloaking and uncloaking of the device is controlled by the modulation signal that turns the modulation transistor on and off, resulting in communication from the device to the reader.

The data stream consists of 154 bits of Manchesterencoded data. The code waveforms are shown in Figure 6-3. The data is sent to the reader by modulating (AM) the carrier signal (13.56 MHz). After completion of the data transmission, the device goes into sleep mode for 100 ms  $\pm$  40%. The device repeats the transmitting and sleep cycles as long as it is energized.

Sleep time is determined by a built-in, low-current timer. The variation of sleep time is approximately  $\pm$  20%. The variation of sleep time between each device results in a randomness of the time slot. Each device wakes up and transmits its data in a different

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MCRF355/360

time slot with respect to each other. Based on this scenario, the reader is able to read many tags that are in the same RF field.

The device has a total of 154 bits of contact reprogrammable memory. All bits are reprogrammable by a contact programmer. A contact programmer (part number PG103003) is available from Microchip Technology Inc. Factory programming prior to shipment, known as Serialized Quick Turn Programming<sup>SM</sup> (SQTP<sup>SM</sup>), is also available. The device is available in die form or packaged in SOIC or PDIP.

**Note:** Information provided herein is preliminary and subject to change without notice.

# **DIE LAYOUT**



Ded Name	Lower	Lower	Upper	Upper	Passivatio	Pad	Pad		
Pau Name	Left X	Left Y	Right X	Right Y	Pad Width Pad Height		Center X	Center Y	
Ant. Pad A	-610.0	489.2	-521.0	578.2	89	89	-565.5	533.7	
Ant. Pad B	-605.0	-579.8	-516.0	-490.8	89	89	-560.5	-535.3	
Vss	-605.0	-58.2	-516.0	30.8	89	89	-560.5	-13.7	
Vdd	463.4	-181.4	552.4	-92.4	89	89	507.9	-136.9	
CLK	463.4	496.8	552.4	585.8	89	89	507.9	541.3	
Vprg	463.4	157.6	552.4	246.6	89	89	507.9	202.1	

# **PAD COORDINATES (MICRONS)**

**Note 1:** All coordinates are referenced from the center of the die. The minimum distance between pads (edge to edge) is 10 mil.

2: Die Size = 1.417 mm x 1.513 mm

Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology Inc.

# 5.0 ELECTRICAL CHARACTERISTICS

\*Notice: Stresses above those listed under "Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

# TABLE 5-1: PAD FUNCTION TABLE

Name	Function
Ant. A	Connected to antenna coil L1
Ant. B	Connected to antenna coils L1 and L2
Vss	Connected to antenna coil L2. Device ground during test mode.
Vdd	DC voltage supply for programming
CLD	Main clock pulse for device
Vprg	Input/Output for programming and read test.

# TABLE 5-2: DC CHARACTERISTICS

All parameters apply across the specified operating ranges, unless otherwise noted.	Commercial (C): Tamb = -20°C to 70°C					
Parameters	Symbol	Min	Тур	Max	Units	Conditions
Reading voltage	Vddr	2.4	—	—	V	VDD voltage for reading
Hysteresis voltage	VHYST	—	TBD	—	TBD	
Operating current	Iddr	—	7	10	μA	VDD = 2.4V during reading at 25°C
Testing voltage	Vddt	—	4	—	V	
Programming voltage: High level input voltage Low level input voltage High voltage	Vih Vil Vhh	0.7 * Vddt —	 20	0.3 * Vddt —	> > >	External DC voltage for program- ming and testing
Current leakage during sleep time	IDD_OFF	—	10		nA	Note
Modulation resistance	Ям	_	3	4	Ω	DC resistance between Drain and Source gates of the modulation transistor (when it is turned on)
Pull-Down resistor	Rpdw	5	8	—	KΩ	CLK and VPRG internal pull-down resistor
Note: This parameter is not tested in production.						

TABLE 5-3:	<b>AC CHARACTERISTICS</b>

All parameters apply across the specified operating ranges, unless otherwise noted.	Commercia	I (C): Tai	mb = -2	0°C to 50 <sup>°</sup>	°C	
Parameters	Symbol	Min	Тур	Max	Units	Conditions
Operating frequency	F <sub>c</sub>	13.5598	13.56	13.5602	MHz	Carrier frequency
Modulation frequency	F <sub>M</sub>	58	70	82	kHz	Manchester
Coil voltage during reading	VPP_AC	4			Vpp	Peak-to-Peak AC voltage across the coil during reading
Coil clamp voltage	VCLMP_AC		32		Vpp	Peak -to-Peak coil clamp voltage
Test mode clock frequency	F <sub>clk</sub>		115	500	kHz	25°C
Sleep time	TOFF	60	100	140	ms	Off time for anticollision feature, at 25°C
Internal resonant capacitor (MCRF360)	Cres	90	100	110	pF	Internal resonant capacitor between Antenna Pad A and Vss (at 13.56 MHz)
Resonant frequency (MCRF360)	FR	12.93	13.56	14.30	MHz	with L = 1.377 $\mu$ H
Write/Erase pulse width	Twc	—	2	10	ms	Time to program bit, at 25°C
Clock high time	Thigh	_	4.4	I	μs	25°C
Clock low time	TLOW		4.4		μs	25°C
Stop condition pulse width	TPW:STO	—	1000	_	ns	25°C
Stop condition setup time	TSU:STO	—	200	_	ns	25°C
Setup time for high voltage	TSU:HH	—	800	_	ns	25°C
High voltage delay time	TDL:HH	—	800		ns	Delay time before the next clock, at 25°C
Data input setup time	TSU:DAT	—	450		ns	25°C
Data input hold time	THD:DAT	—	1.2	—	μs	25°C
Output valid from clock	ΤΑΑ	—	200	—	ns	25°C
Data retention	_	200		_	Years	For T < 120°C

# TABLE 5-4: ABSOLUTE MAXIMUM/MINIMUM RATINGS

Parameters	Symbol	Min	Max	Units	Conditions
Coil current	IPP_AC	—	40	mA	Peak-to-Peak coil current
Maximum Power Dissipation	Рмрр	—	1	W	
Assembly temperature	TASM	—	300	°C	< 10 sec
Storage temperature	TSTORE	-65	150	°C	

# 6.0 FUNCTIONAL DESCRIPTION

The device contains three major sections. The first one is the RF Front-End section, second is the Controller Logic, and third is the Memory section. Figure 6-1 shows the block diagram of the device.

# 6.1 <u>RF Front-End Section</u>

The RF Front-End section includes power supply, power-on-reset, and data modulation circuits.

# 6.1.1 POWER SUPPLY

The power supply circuit generates DC voltage (VDD) by rectifying induced AC coil voltage. The power supply circuit includes high-voltage clamping diodes to prevent excessive voltage development across the antenna coil.

### 6.1.2 POWER-ON-RESET (POR)

This circuit generates a power-on-reset when the tag first enters the reader field. The reset releases when sufficient power has developed on the VDD regulator to allow for correct operation.

# 6.1.3 DATA MODULATION

The data modulation circuit consists of a modulation transistor (MOSFET) and a 1-turn antenna coil (L2). The two are connected in parallel. The transistor is designed to result in less than two ohms (RM) between Antenna Pad B and Vss. As the transistor turns on, the transistor shorts L2 and, therefore, the external LC circuit is detuned (cloaking).

Cloaking and uncloaking occur by driving the transistor on and off, respectively. Therefore, since the data is encoded by a Manchester format, data bit '1' will be sent by uncloaking and cloaking the transistor for 7  $\mu$ s, each. Similarly, data bit '0' will be sent by cloaking and uncloaking the transistor for 7  $\mu$ s, each.



# FIGURE 6-1: BLOCK DIAGRAM

# 6.2 <u>Antenna</u>

The MCRF360 requires an external inductor and capacitance in order to resonate at 13.56 MHz. About one-fourth of the turns of the inductor should be connected between Antenna Pad B and Vss; remaining turns should be connected between Antenna Pad A and Antenna Pad B. The MCRF355 can use a 1.377  $\mu$ H inductor plus 100 pF of external capacitance in order to resonate at 13.56 MHz.

Figure 6-2(a) shows a configuration of an external circuit for the MCRF355. Two external antenna coils (L1 and L2) in series and a capacitor that is connected across the two inductors form a parallel resonant circuit to pick up incoming RF signals and also send back modulated signals to the reader. The first coil (L1) is connected between Antenna Pad A and Antenna Pad B. The second coil (L2) is connected between Antenna Pad B and Vss. The capacitor is connected between Antenna Pad A and Vss.

Figure 6-2(b) shows another configuration of an external circuit for the MCRF355. In this case, the resonant circuit is formed by two capacitors (C1 and C2) and one inductor.

Figure 6-2(c) shows a configuration of an external circuit for MCRF360.



# FIGURE 6-2: CONFIGURATION OF EXTERNAL RESONANT CIRCUITS

# 6.3 <u>Controller Logic</u>

# 6.3.1 CLOCK PULSE GENERATOR

This circuit generates a clock pulse (CLK). The clock pulse is generated by an on-board, time-base oscillator. The clock pulse is used for baud rate timing, data modulation rate, etc.

## 6.3.2 MODULATION LOGIC

This logic acts upon the serial data (154 bits) being read from the memory array. The data is then converted to Manchester code. The code waveforms are shown in Figure 6-3. The encoded data is then fed to the modulation gate in the RF Front-End section. 6.3.3 SLEEP TIMER

This circuit generates a sleep time (100 ms  $\pm$  40%) for the anticollision feature. During this sleep time (TOFF), the modulation transistor remains in a turned-on condition (cloaked) which detunes the LC resonant circuit away from the operating frequency (13.56 MHz).

## 6.3.4 READ/WRITE LOGIC

This logic controls the reading and programming of the memory array.



# FIGURE 6-3: CODE WAVEFORMS

# 7.0 DEVICE PROGRAMMING

MCRF355/360 is a contact programmable device. The device has 154 bits of programmable memory. It can be programmed in the following procedure. (A programmer, part number PG103003, is also available from Microchip.)

# 7.0.1 PROGRAMMING LOGIC

Programming logic is enabled by applying power to the device and clocking the device via the CLK pad while loading the mode code via the VPRG pad (See Examples 7-1 through 7-4 for test definitions). Both the CLK and the VPRG pads have internal pull-down resistors.

# 7.1 Pin Configuration

Connect antenna pads A, B, and Vss to ground.

# 7.2 <u>Pin Timing</u>

- 1. Apply VDDT voltage to VDD. Leave Vss, CLK, and VPRG at ground.
- 2. Load mode code into the VPRG pad. The VPRG is sampled at CLK low to high edge.
- 3. The above mode function (3.2.2) will be executed when the last bit of code is entered.
- 4. Power the device off (VDD = VSS) to exit programming mode.
- 5. An alternative method to exit the programming mode is to bring CLK logic "High" before VPRG to VHH (high voltage).
- 6. Any programming mode can be entered after exiting the current function.

# 7.3 Programming Mode

- 1. Erase EE Code: 0111010100
- 2. Program EE Code: 0111010010
- **3.** Read EE Code: 0111010110
- Note: '0' means logic "Low" (VIL) and '1' means logic "High" (VIH).

# 7.4 Signal Timing

Examples 7-1 through 7-4 show the timing sequence for programming and reading of the device.



# EXAMPLE 7-1: PROGRAMMING MODE 1: ERASE EE

# MCRF355/360



# EXAMPLE 7-3: PROGRAMMING MODE 3: READ EE



# EXAMPLE 7-4: TIMING DATA



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# MCRF355/360 GUIDE PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, please refer to the factory or the listed sales office.



### Sales and Support

#### Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office

2. The Microchip Corporate Literature Center U.S. FAX: (480) 786-7277

3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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# **Microchip Development Kit Sample Format**

Header					13 Byte	es c	of Us	ser	Data				16-Bit (	Che	ecksum		
111111111 0	Customer Number	0	Byte 13	0	Byte 12	0		0	Byte 2	0	Byte 1	0	Checksum	0	Checksum	0	

9 bit header

8 bit customer number

104 bits (13 x 8) of user data

17 bits of zeros between each byte, header, and checksum

16 bits of checksum

Total: 154 bits

#### Notes:

- Users can program all 154 bits of the MCRF355/360. The array can be programmed in any custom format and with any combination of bits.
- The format presented here is used for Microchip microID<sup>TM</sup> Development System (DV103003) and can be ordered as production material with a unique customer number.
- See TB032 for information on ordering custom programmed production material.
- The Microchip Development System (DV103003) uses nine 1's (11111111) as header.
- The preprogrammed tag samples in the development kit have hex 11(= 0001 0001) as the customer number.
- For the development system, users can program the customer number (1 byte) plus the 13 bytes of user data, or they can deselect the "Microchip Format" option in the MicroID<sup>TM</sup> RFLAB and program all 154 bits in any format.
- When users program the samples using the MicroID<sup>TM</sup> RFLAB, the RFLAB calculates the checksum (2 bytes) automatically by adding up all 14 bytes (customer number + 13 bytes of user data), and put into the checksum field in the device memory. See Example 1 for details.
- When the programmed tag is energized by the reader field, the tag outputs all 154 bits of data.
- When the demo reader detects data from the tag, it reports the 14 bytes of the data (customer number plus 13 bytes of user data) to the host computer if the header and checksum are correct. The reader does not send the header and checksum to the host computer.
- The "MicroID<sup>TM</sup> RFLab" or a simple terminal program such as "terminal.exe" can be used to read the reader's output (28 hex digits) on the host computer.
- When the demo reader is used in the terminal mode ("terminal.exe), the tag's data appear after the first two dummy ASCII characters (GG). See Example 2 for details.

# EXAMPLE 7-1: CHECKSUM

Checksum (xxxxxxx xxxxxxxx) = Byte 1 + Byte 2 + .....+ Byte 13 + Customer Number (1 byte)

# EXAMPLE 7-2: READER'S OUTPUT IN TERMINAL MODE ("TERMINAL.EXE")

The demo reader outputs GG+28 hex digits, i.e., GG 12345678901234567890ABCDEFGF.

The first two ASCII characters (GG) are dummy characters.

The tag's data are the next 28 hex digits (112 bits) after the first two ASCII characters (GG).

# TB031

NOTES:



# ГВ032

# MCRF355/360 Factory Programming Support (SQTP<sup>SM</sup>

# INTRODUCTION

The MCRF355 and MCRF360 are 13.56 MHz RF tags which can be contact programmed. The contact programming of the device can be performed by the user or factory-programmed by Microchip Technology, Inc. upon customer request. All 154 bits of data may be programmed in any format or pattern defined by the customer.

For factory programming, ID codes and series numbers must be supplied by the customer or an algorithm may be specified by the customer. This technical brief describes only the case in which identification codes (ID) and series numbers are supplied. The customer may supply the ID codes and series numbers on floppy disk or via email. The codes must conform to the Serialized Quick Turn Programming<sup>SM</sup> (SQTP<sup>SM</sup>) format below:

# FILE SPECIFICATION

SQTP codes supplied to Microchip must comply with the following format:

The ID code file is a plain ASCII text file from floppy disk or email (no headers).

If code files are compressed, they should be self-extracting files.

The code files are used in alphabetical order of their file names (including letters and numbers).

Used (i.e., programmed) code files are discarded by Microchip after use.

Each line of the code file must contain one ID code for one IC.

The code is in hexadecimal format.

The code line is exactly 154 bits (39 hex characters, where the last 2 bits of the last character are don't cares).

Each line must end with a carriage return.

Each hexadecimal ID code must be preceded by a decimal series number.

Series number and ID code must be separated by a space.

The series number must be unique and ascending to avoid double programming.

The series numbers of two consecutive files must also count up for proper linking.



Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology inc.

#### FIGURE 8: EXAMPLE OF TWO SEQUENTIAL CODE FILES

# TB032

NOTES:

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# AN707

# **MCRF 355/360 Applications**

Author: Dr. Youbok Lee, Ph.D. Microchip Technology Inc.

# INTRODUCTION

The MCRF355 passive RFID device is designed for low cost, multiple reading, and various high volume tagging applications using a frequency band of 13.56 MHz. The device has a total of 154 memory bits that can be reprogrammed by a contact programmer. The device operates with a 70 kHz data rate, and asynchronously with respect to the reader's carrier. The device turns on when the coil voltage reaches 4 VPP and outputs data with a Manchester format (see Figure 2-3 in the data sheet). With the given data rate (70 kHz), it takes about 2.2 ms to transmit all 154 bits of the data. After transmitting all data, the device goes into a sleep mode for 100 ms  $\pm$  50%.

The MCRF355 needs only an external parallel LC resonant circuit that consists of an antenna coil and a capacitor for operation. The external LC components must be connected between antenna A, B, and ground pads. The circuit formed between Antenna Pad A and the ground pad must be tuned to the operating frequency of the reader antenna.

# MODE OF OPERATION

The device transmits data by tuning and detuning the resonant frequency of the external circuit. This process is accomplished by using an internal modulation gate (CMOS), that has a very low turn-on resistance ( $2 \sim 4$ 

ohms) between Drain and Source. This gate turns on during a logic "High" period of the modulation signal and off otherwise. When the gate turns on, its low turnon resistance shorts the external circuit between Antenna Pad B and the ground pad. Therefore, the resonant frequency of the circuit changes. This is called *detuned* or *cloaking*. Since the detuned tag is out of the frequency band of the reader, the reader can't see it.

The modulation gate turns off as the modulation signal goes to a logic "Low." This turn-off condition again tunes the resonant circuit to the frequency of the reader antenna. Therefore the reader sees the tag again. This is called *tuned* or *uncloaking*.

The tag coil induces maximum voltage during "uncloaking (tuned)" and minimum voltage during cloaking (detuned). Therefore, the cloaking and uncloaking events develop an amplitude modulation signal in the tag coil.

This amplitude modulated signal in the tag coil perturbs the voltage envelope in the reader coil. The reader coil has maximum voltage during cloaking (detuned) and minimum voltage during uncloaking (tuned). By detecting the voltage envelope, the data signal from the tag can be readily reconstructed.

Once the device transmits all 154 bits of data, it goes into "sleep mode" for about 100 ms. The tag wakes up from sleep time (100 ms) and transmits the data package for 2.2 ms and goes into sleep mode again. The device repeats the transmitting and sleep cycles as long as it is energized.



# FIGURE 1: VOLTAGE ENVELOPE IN READER COIL

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# FIGURE 2: (A) UNCLOAKING (TUNED) AND (B) CLOAKING (DETUNED) MODES AND THEIR RESONANT FREQUENCIES



# ANTICOLLISION FEATURES

During sleep mode, the device remains in a cloaked state where the circuit is detuned. Therefore, the reader can't see the tag during sleep time. While one tag is in sleep mode, the reader can receive data from other tags. This enables the reader to receive clean data from many tags without any data collision. This ability to read multiple tags in the same RF field is called a*nticollision.* Theoretically, more than 50 tags can be read in the same RF field. However, it is affected by distance from the tag to the reader, angular orientation, movement of the tags, and spacial distribution of the tags.





# EXTERNAL CIRCUIT CONFIGURATION

Since the device transmits data by tuning and detuning the antenna circuit, caution must be given in the external circuit configuration. For a better modulation index, the differences between the tuned and detuned frequencies must be wide enough (about 3 ~ 6 MHz).

Figure 4 shows various configurations of the external circuit. The choice of the configuration must be chosen depending on the form-factor of the tag. For example, (a) is a better choice for printed circuit tags while, (b) is a better candidate for coil-wound tags. Both (a) and (b) relate to the MCRF355.

In configuration (a), the tuned resonance frequency is determined by a total capacitance and inductance from Antenna Pad A to Vss. During cloaking, the internal

switch (modulation gate) shorts Antenna Pad B and Vss. Therefore, the inductance L2 is shorted out. As a result, the detuned frequency is determined by the total capacitance and inductance L1. When shorting the inductance between Antenna Pad B and Vss, the detuned (cloak) frequency is higher than the tuned (uncloak) frequency

In configuration (b), the tuned frequency (uncloak) is determined by the inductance L and the total capacitance between Antenna Pad A and Vss. The circuit detunes (cloak) when  $C_2$  is shorted. This detuned frequency (cloak) is lower than the tuned (uncloak) frequency

The MCRF360 includes a 100 pF internal capacitor. This device needs only an external inductor for operation. The explanation on tuning and detuning is the same as for configuration (a).



# FIGURE 4: VARIOUS EXTERNAL CIRCUIT CONFIGURATIONS

# **PROGRAMMING OF DEVICE**

All of the memory bits in the MCRF355/360 are reprogrammable by a contact programmer or by factory programming prior to shipment, known as Serialized Quick Turn Programming<sup>SM</sup> (SQTP<sup>SM</sup>). For more information about contact programming, see page 69 of the *microID*<sup>TM</sup> 13.56 *MHz System Design Guide* (DS21299). For information about SQTP programming, please see TB032 (DS91032), page 19 of the design guide.

Serial Quick Turn Programming (SQTP) is a Service Mark of Microchip Technology Inc.

# AN707

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# AN710

# Antenna Circuit Design

Author: Dr. Youbok Lee, Ph.D. Microchip Technology Inc.

# INTRODUCTION

Passive RFID tags utilize an induced antenna coil voltage for operation. This induced AC voltage is rectified to provide a voltage source for the device. As the DC voltage reaches a certain level, the device starts operating. By providing an energizing RF signal, a reader can communicate with a remotely located device that has no external power source such as a battery. Since the energizing and communication between the reader and tag is accomplished through antenna coils, it is important that the device must be equipped with a proper antenna circuit for successful RFID applications.

An RF signal can be radiated effectively if the linear dimension of the antenna is comparable with the wavelength of the operating frequency. However, the wavelength at 13.56 MHz is 22.12 meters. Therefore, it is difficult to form a true antenna for most RFID applications. Alternatively, a small loop antenna circuit that is resonating at the frequency is used. A current flowing into the coil radiates a near-field magnetic field that falls off with r<sup>-3</sup>. This type of antenna is called a *magnetic* dipole antenna.

For 13.56 MHz passive tag applications, a few microhenries of inductance and a few hundred pF of resonant capacitor are typically used. The voltage transfer between the reader and tag coils is accomplished through inductive coupling between the two coils. As in a typical transformer, where a voltage in the primary coil transfers to the secondary coil, the voltage in the reader antenna coil is transferred to the tag antenna coil and vice versa. The efficiency of the voltage transfer can be increased significantly with high Q circuits.

This section is written for RF coil designers and RFID system engineers. It reviews basic electromagnetic theories on antenna coils, a procedure for coil design, calculation and measurement of inductance, an antenna tuning method, and read range in RFID applications.

# **REVIEW OF A BASIC THEORY FOR RFID ANTENNA DESIGN**

# **Current and Magnetic Fields**

Ampere's law states that current flowing in a conductor produces a magnetic field around the conductor. The magnetic field produced by a current element, as shown in Figure 1, on a round conductor (wire) with a finite length is given by:

# **EQUATION 1:**

$$B_{\phi} = \frac{\mu_o I}{4\pi r} (\cos \alpha_2 - \cos \alpha_1) \qquad (\text{Weber}/m^2)$$

where:

Ι	=	current
r	=	distance from the center of wire
μ <sub>0</sub>	=	permeability of free space and given as $4 \pi \times 10^{-7}$ (Henry/meter)

In a special case with an infinitely long wire where:

$$\alpha_l = -180^\circ$$
$$\alpha_2 = 0^\circ$$

Equation 1 can be rewritten as:

# **EQUATION 2:**

$$B_{\phi} = \frac{\mu_o I}{2\pi r}$$
 (Weber/m<sup>2</sup>)

FIGURE 1: CALCULATION OF MAGNETIC FIELD B AT LOCATION P DUE TO **CURRENT I ON A STRAIGHT** CONDUCTING WIRE



The magnetic field produced by a circular loop antenna is given by:

# **EQUATION 3:**

$$B_{z} = \frac{\mu_{o}INa^{2}}{2(a^{2} + r^{2})^{3/2}}$$
$$= \frac{\mu_{o}INa^{2}}{2} \left(\frac{1}{r^{3}}\right) \text{ for } r^{2} >> a^{2}$$

where

I = current

a = radius of loop

$$r$$
 = distance from the center of wire

$$\mu_0$$
 = permeability of free space and given  
as  $\mu_0 = 4 \pi \times 10^{-7}$  (Henry/meter)

The above equation indicates that the magnetic field strength decays with  $1/r^3$ . A graphical demonstration is shown in Figure 3. It has maximum amplitude in the plane of the loop and directly proportional to both the current and the number of turns, *N*.

Equation 3 is often used to calculate the ampere-turn requirement for read range. A few examples that calculate the ampere-turns and the field intensity necessary to power the tag will be given in the following sections.

# FIGURE 2: CALCULATION OF MAGNETIC FIELD B AT LOCATION P DUE TO CURRENT I ON THE LOOP







# INDUCED VOLTAGE IN AN ANTENNA COIL

Faraday's law states that a time-varying magnetic field through a surface bounded by a closed path induces a voltage around the loop.

Figure 4 shows a simple geometry of an RFID application. When the tag and reader antennas are in close proximity, the time-varying magnetic field *B* that is produced by a reader antenna coil induces a voltage (called electromotive force or simply EMF) in the closed tag antenna coil. The induced voltage in the coil causes a flow of current on the coil. This is called Faraday's law. The induced voltage on the tag antenna coil is equal to the time rate of change of the magnetic flux  $\Psi$ .

# **EQUATION 4:**

$$V = -N \, \frac{d\psi}{dt}$$

where:

N = number of turns in the antenna coil  $\Psi$  = magnetic flux through each turn

The negative sign shows that the induced voltage acts in such a way as to oppose the magnetic flux producing it. This is known as Lenz's Law and it emphasizes the fact that the direction of current flow in the circuit is such that the induced magnetic field produced by the induced current will oppose the original magnetic field.

The magnetic flux  $\Psi$  in Equation 4 is the total magnetic field *B* that is passing through the entire surface of the antenna coil, and found by:

# **EQUATION 5:**

$$\Psi = \int B \cdot dS$$

where:

B =	=	magnetic	field	given	in	Equation	2
-----	---	----------	-------	-------	----	----------	---

*S* = surface area of the coil

= inner product (*cosine angle between two vectors*) of vectors *B* and surface area *S* 

Note:	Both magnetic field B and surface S are					
	vector quantities.					

The presentation of inner product of two vectors in Equation 5 suggests that the total magnetic flux  $\psi$  that is passing through the antenna coil is affected by an orientation of the antenna coils. The inner product of two vectors becomes maximized when the cosine angle between the two are 90 degree, or the two (B field and the surface of coil) are perpendicular to each other. The maximum magnetic flux that is passing through the tag coil is obtained when the two coils (reader coil and tag coil) are placed in parallel with respect to each other. This condition results in maximum induced voltage in the tag coil and also maximum read range. The inner product expression in Equation 5 also can be expressed in terms of a mutual coupling between the reader and tag coils. The mutual coupling between the two coils is maximized in the above condition.

# FIGURE 4: A BASIC CONFIGURATION OF READER AND TAG ANTENNAS IN RFID APPLICATIONS



Using Equations 3 and 5, Equation 4 can be rewritten as:

# **EQUATION 6:**

$$V = -N_2 \frac{d\Psi_{21}}{dt} = -N_2 \frac{d}{dt} \left( \int B \cdot dS \right)$$
$$= -N_2 \frac{d}{dt} \left[ \int \frac{\mu_o i_1 N_1 a^2}{2(a^2 + r^2)^{3/2}} \cdot dS \right]$$
$$= -\left[ \frac{\mu_o N_1 N_2 a^2 (\pi b^2)}{2(a^2 + r^2)^{3/2}} \right] \frac{di_1}{dt}$$
$$= -M \frac{di_1}{dt}$$

where:

- *V* = voltage in the tag coil
- $i_1$  = current on the reader coil
- *a* = radius of the reader coil

b = radius of tag coil

- r = distance between the two coils
- *M* = mutual inductance between the tag and reader coils, and given by:

# **EQUATION 7:**

$$M = \left[\frac{\mu_o \pi N_1 N_2 (ab)^2}{2(a^2 + r^2)^{3/2}}\right]$$

The above equation is equivalent to a voltage transformation in typical transformer applications. The current flow in the primary coil produces a magnetic flux that causes a voltage induction at the secondary coil.

As shown in Equation 6, the tag coil voltage is largely dependent on the mutual inductance between the two coils. The mutual inductance is a function of coil geometry and the spacing between them. The induced voltage in the tag coil decreases with  $r^{-3}$ . Therefore, the read range also decreases in the same way.

From Equations 4 and 5, a generalized expression for induced voltage  $V_o$  in a tuned loop coil is given by:

# **EQUATION 8:**

$$V_0 = 2\pi f N S Q B_o \cos \alpha$$

#### where:

f	=	frequency of the arrival signal
Ν	=	number of turns of coil in the loop

S = area of the loop in square meters (m<sup>2</sup>)

Q = quality factor of circuit

$$B_0$$
 = strength of the arrival signal

$$\alpha$$
 = angle of arrival of the signal

In the above equation, the quality factor Q is a measure of the selectivity of the frequency of the interest. The Q will be defined in Equations 31 through 47.





The induced voltage developed across the loop antenna coil is a function of the angle of the arrival signal. The induced voltage is maximized when the antenna coil is placed in parallel with the incoming signal where  $\alpha = 0$ .

# EXAMPLE 1: CALCULATION OF B-FIELD IN A TAG COIL

The MCRF355 device turns on when the antenna coil develops 4 VPP across it. This voltage is rectified and the device starts to operate when it reaches 2.4 VDC. The B-field to induce a 4 VPP coil voltage with an ISO standard 7810 card size ( $85.6 \times 54 \times 0.76$  mm) is calculated from the coil voltage equation using Equation 8.

# **EQUATION 9:**

$$V_o = 2\pi f N S Q B_o \cos \alpha = 4$$

and

$$B_o = \frac{4/(\sqrt{2})}{2\pi f N S Q \cos \alpha} = 0.0449 \qquad (\mu w b m^{-2})$$

where the following parameters are used in the above calculation:

Tag coil size	=	$(85.6 \times 54) \text{ mm}^2$ (ISO card size) = 0.0046224 m <sup>2</sup>
Frequency	=	13.56 MHz
Number of turns	=	4
${\it Q}$ of tag antenna coil	=	40
AC coil voltage to turn on the tag	=	4 Vpp
$\cos \alpha =$	=	1 (normal direction, $\alpha = 0$ ).

# EXAMPLE 2: NUMBER OF TURNS AND CURRENT (AMPERE-TURNS)

Assuming that the reader should provide a read range of 15 inches (38.1 cm) for the tag given in the previous example, the current and number of turns of a reader antenna coil is calculated from Equation 3:

**EQUATION 10:** 

$$(NI)_{rms} = \frac{2B_z(a^2 + r^2)^{3/2}}{\mu a^2}$$
$$= \frac{2(0.0449 \times 10^{-6})(0.1^2 + (0.38)^2)^{3/2}}{(4\pi \times 10^{-7})(0.1^2)}$$

= 0.43(ampere - turns)

The above result indicates that it needs a 430 mA for 1 turn coil, and 215 mA for 2-turn coil.

# EXAMPLE 3: OPTIMUM COIL DIAMETER OF THE READER COIL

An optimum coil diameter that requires the minimum number of ampere-turns for a particular read range can be found from Equation 3 such as:

**EQUATION 11:** 

$$NI = K \frac{(a^2 + r^2)^{\frac{3}{2}}}{a^2}$$

 $K = \frac{2B_z}{\mu_o}$ 

where:

By taking derivative with respect to the radius *a*,

$$\frac{d(NI)}{da} = K \frac{3/2(a^2 + r^2)^{1/2}(2a^3) - 2a(a^2 + r^2)^{3/2}}{a^4}$$
$$= K \frac{(a^2 - 2r^2)(a^2 + r^2)^{1/2}}{a^3}$$

The above equation becomes minimized when:

$$a^2 - 2r^2 = 0$$

The above result shows a relationship between the read range vs. optimum coil diameter. The optimum coil diameter is found as:

 $a = \sqrt{2}r$ 

# **EQUATION 12:**

where:

$$a = radius of coil$$
  
 $r = read range.$ 

The result indicates that the optimum loop radius, a, is 1.414 times the demanded read range r.

# WIRE TYPES AND OHMIC LOSSES

## Wire Size and DC Resistance

The diameter of electrical wire is expressed as the American Wire Gauge (AWG) number. The gauge number is inversely proportional to diameter, and the diameter is roughly doubled every six wire gauges. The wire with a smaller diameter has a higher DC resistance. The DC resistance for a conductor with a uniform cross-sectional area is found by:

# **EQUATION 13:**

$$R_{DC} = \frac{l}{\sigma S} \qquad (\Omega)$$

where:

l =total length of the wire

 $\sigma$  = conductivity

S = cross-sectional area

Table 1 shows the diameter for bare and enamel-coated wires, and DC resistance.

### **AC Resistance of Wire**

At DC, charge carriers are evenly distributed through the entire cross section of a wire. As the frequency increases, the reactance near the center of the wire increases. This results in higher impedance to the current density in the region. Therefore, the charge moves away from the center of the wire and towards the edge of the wire. As a result, the current density decreases in the center of the wire and increases near the edge of the wire. This is called a *skin effect*. The depth into the conductor at which the current density falls to 1/e, or 37% of its value along the surface, is known as the *skin depth* and is a function of the frequency and the permeability and conductivity of the medium. The skin depth is given by:

# **EQUATION 14:**

$$\delta = \frac{1}{\sqrt{\pi f \mu \sigma}}$$

where:

f = frequency

- $\mu$  = permeability of material
- $\sigma$  = conductivity of the material

# EXAMPLE 4:

The skin depth for a copper wire at 13.56 MHz can be calculated as:

# **EQUATION 15:**

$$\delta = \frac{1}{\sqrt{\pi f (4\pi \times 10^{-7})(5.8 \times 10^{-7})}}$$
$$= \frac{0.0179}{\sqrt{f}} \qquad (m)$$
$$= 0.187 \qquad (mm)$$

The wire resistance increases with frequency, and the resistance due to the skin depth is called an AC resistance. An approximated formula for the AC resistance is given by:

# **EQUATION 16:**

$$R_{ac} \approx \frac{1}{2\sigma\pi\delta} = (R_{DC})\frac{a}{2\delta}$$
 (Ω)

where:
TABLE 1: AWG WIRE CHART

Wire Size (AWG)	Dia. in Mils (bare)	Dia. in Mils (coated)	Ohms/ 1000 ft.	Cross Section (mils)
1	289.3	—	0.126	83690
2	287.6	_	0.156	66360
3	229.4	_	0.197	52620
4	204.3	—	0.249	41740
5	181.9	_	0.313	33090
6	162.0	_	0.395	26240
7	166.3	—	0.498	20820
8	128.5	131.6	0.628	16510
9	114.4	116.3	0.793	13090
10	101.9	106.2	0.999	10380
11	90.7	93.5	1.26	8230
12	80.8	83.3	1.59	6530
13	72.0	74.1	2.00	5180
14	64.1	66.7	2.52	4110
15	57.1	59.5	3.18	3260
16	50.8	52.9	4.02	2580
17	45.3	47.2	5.05	2060
18	40.3	42.4	6.39	1620
19	35.9	37.9	8.05	1290
20	32.0	34.0	10.1	1020
21	28.5	30.2	12.8	812
22	25.3	28.0	16.2	640
23	22.6	24.2	20.3	511
24	20.1	21.6	25.7	404
25	17.9	19.3	32.4	320

Wire Size (AWG)	Dia. in Mils (bare)	Dia. in Mils (coated)	Ohms/ 1000 ft.	Cross Section (mils)
26	15.9	17.2	41.0	253
27	14.2	15.4	51.4	202
28	12.6	13.8	65.3	159
29	11.3	12.3	81.2	123
30	10.0	11.0	106.0	100
31	8.9	9.9	131	79.2
32	8.0	8.8	162	64.0
33	7.1	7.9	206	50.4
34	6.3	7.0	261	39.7
35	5.6	6.3	331	31.4
36	5.0	5.7	415	25.0
37	4.5	5.1	512	20.2
38	4.0	4.5	648	16.0
39	3.5	4.0	847	12.2
40	3.1	3.5	1080	9.61
41	2.8	3.1	1320	7.84
42	2.5	2.8	1660	6.25
43	2.2	2.5	2140	4.84
44	2.0	2.3	2590	4.00
45	1.76	1.9	3350	3.10
46	1.57	1.7	4210	2.46
47	1.40	1.6	5290	1.96
48	1.24	1.4	6750	1.54
49	1.11	1.3	8420	1.23
50	0.99	1.1	10600	0.98

Note: 1 mil =  $2.54 \times 10^{-3}$  cm

Note:  $1 \text{ mil} = 2.54 \text{ x} 10^{-3} \text{ cm}$ 

#### INDUCTANCE OF VARIOUS ANTENNA COILS

An electric current element that flows through a conductor produces a magnetic field. This time-varying magnetic field is capable of producing a flow of current through another conductor – this is called *inductance*. The inductance L depends on the physical characteristics of the conductor. A coil has more inductance than a straight wire of the same material, and a coil with more turns has more inductance than a coil with fewer turns. The inductance L of inductor is defined as the ratio of the total magnetic flux linkage to the current I through the inductor:

#### **EQUATION 17:**

$$L = \frac{N\psi}{I}$$
 (Henry)

where:

N = number of turns I = current  $\Psi$  = the magnetic flux

For a coil with multiple turns, the inductance is greater as the spacing between turns becomes smaller. Therefore, the tag antenna coil that has to be formed in a limited space often needs a multilayer winding to reduce the number of turns.

#### **Calculation of Inductance**

Inductance of the coil can be calculated in many different ways. Some are readily available from references<sup>[1-4]</sup>. It must be remembered that for RF coils the actual resulting inductance may differ from the calculated true result because of distributed capacitance. For that reason, inductance calculations are generally used only for a starting point in the final design.

#### Inductance of a Straight Wound Wire

The inductance of a straight wound wire shown in Figure 1 is given by:

#### **EQUATION 18:**

$$L = 0.002l \left[ \log_e \frac{2l}{a} - \frac{3}{4} \right] \qquad (\mu H)$$

where:

*l* and *a* = length and radius of wire in cm, respectively.

#### EXAMPLE 5: INDUCTANCE CALCULATION FOR A STRAIGHT WIRE:

The inductance of a wire with 10 feet (304.8cm) long and 2 mm in diameter is calculated as follows:

**EQUATION 19:** 

$$L = 0.002(304.8) \left[ \ln\left(\frac{2(304.8)}{0.1}\right) - \frac{3}{4} \right]$$

 $= 4.855(\mu H)$ 

# Inductance of Thin Film Inductor with a Rectangular Cross Section

Inductance of a conductor with rectangular cross section as shown in Figure 6 is calculated as:





#### **EQUATION 20:**

$$L = 0.002l \left\{ \ln\left(\frac{2l}{a+b}\right) + 0.50049 + \frac{a+b}{3l} \right\} \qquad (\mu H)$$

where:

a =width in cm

*b* = thickness in cm

l = length of conductor in cm

#### Inductance of a Circular Coil with Single Turn

The inductance of a circular coil shown in Figure 7 can be calculated by:





**EQUATION 21:** 

$$L = 0.01257(a) \left[ 2.303 \log_{10} \left( \frac{16a}{d} - 2 \right) \right] \qquad (\mu H)$$

where:

*a* = mean radius of loop in (cm)

d = diameter of wire in (cm)

#### Inductance of an N-turn Circular Coil with Single Layer

The inductance of a circular coil with single layer is calculated as:

#### **EQUATION 22:**

$$L = \frac{(aN)^2}{22.9l + 25.4a} \qquad (\mu H)$$

where:

l = length

*a* = the radius of coil in cm

Inductance of N-turn Circular Coil with Multilayer





Figure 8 shows an N-turn inductor of circular coil with multilayer. Its inductance is calculated by:

#### **EQUATION 23:**

$$L = \frac{0.31(aN)^2}{6a + 9h + 10b} \qquad (\mu H)$$

where:

Ν

- *a* = average radius of the coil in cm
  - number of turns
- *b* = winding thickness in cm
- h = winding height in cm

# Inductance of Spiral Wound Coil with Single Layer

The inductance of a spiral inductor is calculated by:

#### **EQUATION 24:**

$$L = \frac{(aN)^2}{8a+11b} \qquad (\mu H)$$





#### Inductance of N-turn Square Loop Coil with Multilayer

Inductance of a multilayer square loop coil is calculated by:

#### **EQUATION 25:**

$$L = 0.008 a N^2 \left\{ 2.303 \log_{10} \left( \frac{a}{b+c} \right) + 0.2235 \frac{b+c}{a} + 0.726 \right\} (\mu H)$$

where:

- N = number of turns
- *a* = side of square measured to the center of the rectangular cross section of winding
- b =winding length
- c = winding depth as shown in Figure 10.

Note: All dimensions are in cm.





#### Inductance of a Flat Square Coil

Inductance of a flat square coil of rectangular cross section with N turns is calculated by<sup>[4]</sup>:

#### **EQUATION 26:**

$$L = 0.0467aN^{2} \left\{ \log_{10} \left( 2\frac{a^{2}}{t+w} \right) - \log_{10} (2.414a) \right\} + 0.02032aN^{2} \left\{ 0.914 + \left[ \frac{0.2235}{a} (t+w) \right] \right\}$$

where:

а

L =	= in	μH
-----	------	----

- = side length in inches
- t =thickness in inches

w =width in inches

#### FIGURE 11: SQUARE LOOP INDUCTOR WITH A RECTANGULAR CROSS SECTION



The formulas for inductance are widely published and provide a reasonable approximation for the relationship between inductance and the number of turns for a given physical size<sup>[1-4]</sup>. When building prototype coils, it is wise to exceed the number of calculated turns by about 10% and then remove turns to achieve a right value. For production coils, it is best to specify an inductance and tolerance rather than a specific number of turns.

#### CONFIGURATION OF ANTENNA CIRCUITS

#### **Reader Antenna Circuits**

The inductance for the reader antenna coil for 13.56 MHz is typically in the range of a few microhenries ( $\mu$ H). The antenna can be formed by aircore or ferrite core inductors. The antenna can also be formed by a metallic or conductive trace on PCB board or on flexible substrate.

The reader antenna can be made of either a single coil, that is typically forming a series or a parallel resonant circuit, or a double loop (transformer) antenna coil. Figure 12 shows various configurations of reader antenna circuit. The coil circuit must be tuned to the operating frequency to maximize power efficiency. The tuned LC resonant circuit is the same as the bandpass filter that passes only a selected frequency. The Q of the tuned circuit is related to both read range and bandwidth of the circuit. More on this subject will be discussed in the following section.

Choosing the size and type of antenna circuit depends on the system design topology. The series resonant circuit results in minimum impedance at the resonance frequency. Therefore, it draws a maximum current at the resonance frequency. Because of its simple circuit topology and relatively low cost, this type of antenna circuit is suitable for proximity reader antenna.

On the other hand, a parallel resonant circuit results in maximum impedance at the resonance frequency. Therefore, maximum voltage is available at the resonance frequency. Although it has a minimum resonant current, it still has a strong circulating current that is proportional to Q of the circuit. The double loop antenna coil that is formed by two parallel antenna circuits can also be used.

The frequency tolerance of the carrier frequency and output power level from the read antenna is regulated by government regulations (e.g., FCC in the USA).

FCC limits for 13.56 MHz frequency band are as follows:

- 1. Tolerance of the carrier frequency: 13.56 MHz  $\pm$  +/- 0.01% =  $\pm$ /- 1.356 kHz.
- 2. Frequency bandwidth: +/- 7 kHz.
- 3. Power level of fundamental frequency: 10 mv/m at 30 meters from the transmitter.
- 4. Power level for harmonics: -50.45 dB down from the fundamental signal.

The transmission circuit including the antenna coil must be designed to meet the FCC limits.

#### FIGURE 12: VARIOUS READER ANTENNA CIRCUITS



#### **Tag Antenna Circuits**

The MCRF355 device communicates data by tuning and detuning the antenna circuit (see AN707). Figure 13 shows examples of the external circuit arrangement.

The external circuit must be tuned to the resonant frequency of the reader antenna. In a detuned condition, a circuit element between the antenna B and Vss pads is shorted. The frequency difference (delta frequency) between tuned and detuned frequencies must be adjusted properly for optimum operation. It has been found that maximum modulation index and maximum read range occur when the tuned and detuned frequencies are separated by 3 to 6 MHz.

The tuned frequency is formed from the circuit elements between the antenna A and Vss pads without shorting the antenna B pad. The detuned frequency is found when the antenna B pad is shorted. This detuned frequency is calculated from the circuit between antenna A and Vss pads excluding the circuit element between antenna B and Vss pads.

In Figure 13 (a), the tuned resonant frequency is

#### **EQUATION 27:**

$$f_o = \frac{1}{2\pi \sqrt{L_T C}}$$

where:

 $L_T$  = L<sub>1</sub> + L<sub>2</sub> + 2L<sub>M</sub> = Total inductance between antenna A and Vss pads

*L<sub>I</sub>* = inductance between antenna A and antenna B pads

 $L_2$  = inductance between ant. B and Vss pads

*M* = mutual inductance between coil 1 and coil 2

$$= k_{\sqrt{L_1 L_2}}$$

- *k* = coupling coefficient between the two coils
- C = tuning capacitance

and detuned frequency is

#### **EQUATION 28:**

$$f_{detuned} = \frac{1}{2\pi \sqrt{L_1 C}}$$

In this case,  $f_{detuned}$  is higher than  $f_{tuned}$ .

Figure 13(b) shows another example of the external circuit arrangement. This configuration controls  $C_2$  for tuned and detuned frequencies. The tuned and untuned frequencies are

#### **EQUATION 29:**

$$f_{tuned} = \frac{1}{2\pi \sqrt{\left(\frac{C_1 C_2}{C_1 + C_2}\right)L}}$$

and

#### **EQUATION 30:**

$$f_{detuned} = \frac{1}{2\pi \sqrt{LC_1}}$$

A typical inductance of the coil is about a few microhenry with a few turns. Once the inductance is determined, the resonant capacitance is calculated from the above equations. For example, if a coil has an inductance of 1.3  $\mu$ H, then it needs a 106 pF of capacitance to resonate at 13.56 MHz.

# CONSIDERATION ON QUALITY FACTOR Q AND BANDWIDTH OF TUNING CIRCUIT

The voltage across the coil is a product of quality factor Q of the circuit and input voltage. Therefore, for a given input voltage signal, the coil voltage is directly proportional to the Q of the circuit. In general, a higher Q

results in longer read range. However, the Q is also related to the bandwidth of the circuit as shown in the following equation.

#### **EQUATION 31:**

$$Q = \frac{f_o}{B}$$



#### FIGURE 13: VARIOUS EXTERNAL CIRCUIT CONFIGURATIONS

# Bandwidth requirement and limit on circuit *Q* for MCRF355

Since the MCRF355 operates with a data rate of 70 kHz, the reader antenna circuit needs a bandwidth of at least twice of the data rate. Therefore, it needs:

#### **EQUATION 32:**

$$B_{minimum} = 140 \text{ kHz}$$

Assuming the circuit is turned at 13.56 MHz, the maximum attainable Q is obtained from Equations 31 and 32:

#### **EQUATION 33:**

$$Q_{max} = \frac{f_o}{B} = 96.8$$

In a practical LC resonant circuit, the range of Q for 13.56 MHz band is about 40. However, the Q can be significantly increased with a ferrite core inductor. The system designer must consider the above limits for optimum operation.

#### **RESONANT CIRCUITS**

Once the frequency and the inductance of the coil are determined, the resonant capacitance can be calculated from:

#### **EQUATION 34:**

$$C = \frac{1}{L(2\pi f_o)^2}$$

In practical applications, parasitic (distributed) capacitance is present between turns. The parasitic capacitance in a typical tag antenna coil is a few (pF). This parasitic capacitance increases with operating frequency of the device.

There are two different resonant circuits: parallel and series. The parallel resonant circuit has maximum impedance at the resonance frequency. It has a minimum current and maximum voltage at the resonance frequency. Although the current in the circuit is minimum at the resonant frequency, there are a circulation current that is proportional to Q of the circuit. The parallel resonant circuit is used in both the tag and the high-power reader antenna circuit.

On the other hand, the series resonant circuit has a minimum impedance at the resonance frequency. As a result, maximum current is available in the circuit. Because of its simplicity and the availability of the high current into the antenna element, the series resonant circuit is often used for a simple proximity reader.

#### **Parallel Resonant Circuit**

Figure 14 shows a simple parallel resonant circuit. The total impedance of the circuit is given by:

#### **EQUATION 35:**

$$Z(j\omega) = \frac{j\omega L}{(1-\omega^2 LC) + j\frac{\omega L}{R}} \quad (\Omega)$$

where  $\omega$  is an angular frequency given as  $\omega = 2\pi f$ .

The maximum impedance occurs when the denominator in the above equation is minimized. This condition occurs when:

#### **EQUATION 36:**

$$\omega^2 LC = 1$$

This is called a resonance condition, and the resonance frequency is given by:

#### **EQUATION 37:**

$$f_0 = \frac{1}{2\pi \sqrt{LC}}$$

By applying Equation 36 into Equation 35, the impedance at the resonance frequency becomes:

#### **EQUATION 38:**

Z = R

where R is the load resistance.

#### FIGURE 14: PARALLEL RESONANT CIRCUIT



The R and C in the parallel resonant circuit determine the bandwidth, B, of the circuit.

#### **EQUATION 39:**

$$B = \frac{1}{2\pi RC} \qquad (Hz)$$

The quality factor, Q, is defined by various ways such as

#### **EQUATION 40:**

$$Q = \frac{\text{Energy Stored in the System per One Cycle}}{\text{Energy Dissipated in the System per One Cycle}}$$

 $= \frac{reactance}{resistance}$ 



 $=\frac{f_0}{B}$ 

#### where:

ω	=	$2\pi f$ = angular frequency
$f_o$	=	resonant frequency
В	=	bandwidth
r	=	ohmic losses

By applying Equation 37 and Equation 39 into Equation 40, the Q in the parallel resonant circuit is:

#### **EQUATION 41:**

$$Q = R_{\sqrt{\frac{C}{L}}}$$

The Q in a parallel resonant circuit is proportional to the load resistance R and also to the ratio of capacitance and inductance in the circuit.

When this parallel resonant circuit is used for the tag antenna circuit, the voltage drop across the circuit can be obtained by combining Equations 8 and 41:

#### EQUATION 42:

$$V_o = 2\pi f_o NQSB_o \cos \alpha$$
$$= 2\pi f_0 N \left( R \sqrt{\frac{C}{L}} \right) SB_0 \cos \alpha$$

The above equation indicates that the induced voltage in the tag coil is inversely proportional to the square root of the coil inductance, but proportional to the number of turns and surface area of the coil.

#### **Series Resonant Circuit**

A simple series resonant circuit is shown in Figure 15. The expression for the impedance of the circuit is:

#### **EQUATION 43:**

$$Z(j\omega) = r + j(X_L - X_C) \qquad (\Omega)$$

where:

- a dc ohmic resistance of coil and capacitor
- $X_L and X_C$  = the reactance of the coil and capacitor, respectively, such that:

#### **EQUATION 44:**

$$X_L = 2\pi f_o L \qquad (\Omega)$$

#### **EQUATION 45:**

$$X_c = \frac{1}{2\pi f_o C} \qquad (\Omega)$$

The impedance in Equation 43 becomes minimized when the reactance component cancelled out each other such that  $X_L = X_C$ . This is called a resonance condition. The resonance frequency is same as the parallel resonant frequency given in Equation 37.

#### 

The half power frequency bandwidth is determined by r and L, and given by:

#### **EQUATION 46:**

$$B = \frac{r}{2\pi L} \qquad (Hz)$$

The quality factor, Q, in the series resonant circuit is given by:

$$Q = \frac{f_0}{B} = \frac{\omega L}{r} = \frac{1}{r\omega C}$$

The series circuit forms a voltage divider, the voltage drops in the coil is given by:

#### **EQUATION 47:**

$$V_o = \frac{jX_L}{r + jX_L - jX_c} V_{in}$$

When the circuit is tuned to a resonant frequency such as  $X_L = X_{C_1}$  the voltage across the coil becomes:

#### **EQUATION 48:**

$$V_o = \frac{jX_L}{r}V_{in}$$
$$= jQV_{in}$$

The above equation indicates that the coil voltage is a product of input voltage and Q of the circuit. For example, a circuit with Q of 40 can have a coil voltage that is 40 times higher than input signal. This is because all energy in the input signal spectrum becomes squeezed into a single frequency band.

#### EXAMPLE 6: CIRCUIT PARAMETERS

If the DC ohmic resistance r is 5 
$$\Omega$$
, then the *L* and *C* values for 13.56 MHz resonant circuit with  $Q = 40$  are:  
**EQUATION 49:**  
 $X_L = Qr_s = 200\Omega$ 

$$L = \frac{X_L}{2\pi f} = \frac{200}{2\pi (13.56MHz)} = 2.347 \qquad (\mu H)$$
$$C = \frac{1}{2\pi f X_L} = \frac{1}{2\pi (13.56 \text{ MHz})(200)} = 58.7 \text{ (pF)}$$

#### **TUNING METHOD**

The circuit must be tuned to the resonance frequency for a maximum performance (read range) of the device. Two examples of tuning the circuit are as follows:

#### • Voltage Measurement Method:

- a) Set up a voltage signal source at the resonance frequency.
- b) Connect a voltage signal source across the resonant circuit.
- c) Connect an Oscilloscope across the resonant circuit.
- d) Tune the capacitor or the coil while observing the signal amplitude on the Oscilloscope.
- e) Stop the tuning at the maximum voltage.

- S-parameter or Impedance Measurement Method using Network Analyzer:
  - a) Set up an S-Parameter Test Set (Network Analyzer) for S11 measurement, and do a calibration.
  - b) Measure the S11 for the resonant circuit.
  - c) Reflection impedance or reflection admittance can be measured instead of the S11.
  - d) Tune the capacitor or the coil until a maximum null (S11) occurs at the resonance frequency, f<sub>o</sub>. For the impedance measurement, the maximum peak will occur for the parallel resonant circuit, and minimum peak for the series resonant circuit.





#### FIGURE 17: FREQUENCY RESPONSES FOR RESONANT CIRCUIT



- **Note 1:** (a) S11 Response, (b) Impedance Response for a Parallel Resonant Circuit, and (c) Impedance Response for a Series Resonant Circuit.
  - 2: In (a), the null at the resonance frequency represents a minimum input reflection at the resonance frequency. This means the circuit absorbs the signal at the frequency while other frequencies are reflected back. In (b), the impedance curve has a peak at the resonance frequency. This is because the parallel resonant circuit has a maximum impedance at the resonance frequency. (c) shows a response for the series resonant circuit. Since the series resonant circuit has a minimum impedance at the resonance frequency, a minimum peak occurs at the resonance frequency.

#### **READ RANGE OF RFID DEVICES**

Read range is defined as a maximum communication distance between the reader and tag. In general, the read range of passive RFID products varies, depending on system configuration and is affected by the following parameters:

- a) Operating frequency and performance of antenna coils
- b) Q of antenna and tuning circuit
- c) Antenna orientation
- d) Excitation current
- e) Sensitivity of receiver
- f) Coding (or modulation) and decoding (or demodulation) algorithm
- g) Number of data bits and detection (interpretation) algorithm
- h) Condition of operating environment (electrical noise), etc.

The read range of 13.56 MHz is relatively longer than that of 125 kHz device. This is because the antenna efficiency increases as the frequency increases. With a given operating frequency, the conditions (a - c) are related to the antenna configuration and tuning circuit. The conditions (d - e) are determined by a circuit topology of reader. The condition (f) is a communication protocol of the device, and (g) is related to a firmware software program for data detection.

Assuming the device is operating under a given condition, the read range of the device is largely affected by the performance of the antenna coil. It is always true that a longer read range is expected with the larger size of the antenna with a proper antenna design. Figures 18 and 19 show typical examples of the read range of various passive RFID devices.



#### FIGURE 18: READ RANGE VS. TAG SIZE FOR TYPICAL PROXIMITY APPLICATIONS\*





Note: Actual results may be shorter or longer than the range shown, depending upon factors discussed above.

#### REFERENCES

- [1] V. G. Welsby, The Theory and Design of Inductance Coils, John Wiley and Sons, Inc., 1960.
- [2] Frederick W. Grover, Inductance Calculations Working Formulas and Tables, Dover Publications, Inc., New York, NY., 1946.
- [3] Keith Henry, Editor, Radio Engineering Handbook, McGraw-Hill Book Company, New York, NY., 1963.
- [4] James K. Hardy, High Frequency Circuit Design, Reston Publishing Company, Inc.Reston, Virginia, 1975.

# Місвоснір microID™ 13.56 MHz DESIGN GUIDE

### 13.56 MHz Reader Reference Design

#### 1.0 INTRODUCTION

This chapter provides a reference guide for the 13.56 MHz reader designer. The schematic included in this chapter is for the 13.56 MHz Reference Reader included in the DV103003 microID<sup>TM</sup> Developer's Kit. The circuit is designed for short read-range applications. The basic design can be modified for long-range or other applications with MCRF355/360 devices. An electronic copy of the PICmicro<sup>®</sup> microcontroller source code is available upon request.

#### 2.0 READER CIRCUITS

The RFID reader consists of transmitting and receiving sections. It transmits a carrier signal (13.56 MHz), receives the backscattered signal from the tag, and performs data processing. The reader also communicates with an external host computer. A basic block diagram of a typical RFID reader is shown in Figure 2-1.

The transmitting section contains a 13.56 MHz signal oscillator (74HC04), power amplifier (Q2), and RF tuning circuits. The tuning circuit matches impedance between the antenna coil circuit and the power driver at 13.56 MHz. The radiating signal strength from the antenna must comply with government regulations. For best performance, the antenna coil circuit must be tuned to the same frequency of the tag. The design for antenna circuits is given in Application Note AN710 (DS00710).

The receiving section contains an envelope detector (D6), hi-pass filters, and amplifiers (U2 and U3). When the tag is energized, it transmits 154 bits of data that is encoded in Biphase-L (Manchester). In the Manchester encoding, data '1' is represented by a logic high-to-low level change at midclock, and data '0' is represented by a low-to-high level change at midclock. There is always a level change at middle of every bit clock.





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#### FIGURE 2-2: SIGNAL WAVEFORMS



#### FIGURE 2-3: BIPHASE-L (MANCHESTER) SIGNAL



When the tag is energized by the reader's carrier signal, it transmits back with an amplitude modulated signal. This results in a perturbation in the voltage amplitude across the reader antenna coil. The envelope detector detects the changes in the voltage amplitude and passes it into an RC filter (R7, C11). The charged signal in the capacitor passes through active filters and amplifiers. The signal that is passing through this receiving section is the data signal. This filteredshaped data signal is fed into Pin 10 of the microcontroller for data processing.

#### 2.1 <u>FCC Specifications on Transmitting</u> <u>Signal</u>

Each country limits the signal strength of the radio frequency signal that is intentionally radiated from the device. In the USA, the maximum signal strength that is radiated from the device is regulated by Federal Communication Commission (FCC). Any device operating at 13.56 MHz frequency band must comply with the FCC Part 15.225 of the federal regulation. FCC limits for 13.56 MHz frequency band are al follows:

- 1. Tolerance of the carrier frequency: 13.56 MHz +/- 0.01% = +/- 7 kHz.
- 2. Frequency bandwidth: +/- 7 kHz.
- 3. Power level of fundamental frequency: 10 mv/m at 30 meters from the transmitter.
- 4. Power level for harmonics: -50.45 dB down from the fundamental signal.

The transmission circuit including the antenna coil must be designed to meet the FCC limits.

#### 3.0 OPTIMIZATION FOR LONG-RANGE APPLICATIONS

The reader circuit provided is designed for about a 5-inch read-range, using a 2-inch by 2-inch tag coil that is printed on PCB with the MCRF355. The read-range can be increased by increasing the reader power, sensitivity, and antenna size. A read-range of more than 30-inches can be achieved with the MCRF355 and an optimized reader. In order to optimize the reader circuit for long-range applications, the following aspects may be considered:

- Optimize the output power level within FCC limits. The reader should provide a sufficient signal level to the tag. The tag needs about 4 VPP across the coil circuit for operation. The power level radiating from the reader antenna must comply to the government regulations such as FCC specifications in the USA. The FCC limits for 13.56 MHz band are described in Section 2.1. For long-range applications, the designer may start with about 50 VPP of antenna voltage and optimize the signal strength for a read-range within the government regulations.
- 2. Increase the size of the antenna. The readrange, in general, is proportional to the size of the reader coil (see Equation 12 in Application Note 710). An optimum radius of antenna is 1.414 times of the read-range.
- 3. Increase the Q of the antenna circuit. The read-range increases with Q of the antenna circuit. This is because the induced voltage is directly proportional to Q of the circuit. The recommended Q for long-range applications is as follows:

40 < Q < 96 for reader 40 < Q for tag

- Optimize the input sensitivity of the reader. 4 The sensitivity is a measure of how weak a signal can be and still be satisfactorily received. The sensitivity is proportional to the carrier power and square of the modulation index (1 for 100% modulation such as MCRF355). It is inversely proportional to the noise signal. The limit to the sensitivity of the receiving section of the reader is noise, both external and internal. The external noises may come from various sources such as computers, televisions, appliances, motors, power lines, transformers, etc. The internal noise is mostly due to a thermal noise of components. To reduce noise, the reader should be operated a distance away from the noise sources. The receiving section may have a 70 kHz bandpass filter to reduce the noises. The 70 kHz bandpass filter will pass only the 70 kHz data signal for processing. The receiving section should have sensitivity of about -120 dBm for long-range applications.
- 5. Optimize the amplitude gain circuit. The receiving circuit amplifies the modulated signals before data processing. The input signal contains both real data and noise. Typically, op amplifiers are used for both as a gain amplifier and filter. The gain must be optimized within the circuit to obtain gains only at the real data signal.

#### 4.0 READER SCHEMATIC



#### 5.0 READER BILL OF MATERIALS

Assembly #	Line #	Qty	Part #	Part Description	Reference Designator
02-01523	1	1	02-01523-D	PCB ASSY DWG, MCRF355 microID READER	
02-01523	2	1	03-01523	SCHEMATIC, MCRF355 microID READER	
02-01523	3	1	04-01523	PCB FABRICATION, MCRF355 microID READER	
02-01523	4	2	MM74HC04M	IC, SMT, CMOS HEX INVERTER, 14P SOIC	U1, U8
02-01523	5	1	LF347M	IC, SMT, QUAD BI-FET OP AMP, 14P SOIC	U2
02-01523	6	1	LM339M	IC, SMT, LOW POWER LOW OFFSET VOLT QUAD COMPARATORS,14P SOIC	U3
02-01523	7	1	PIC16C558-20/ SO	IC, PIC16C558-20/SO EPROM-BASED 8-BIT CMOS MICROCONTROLLER	U4
02-01523	8	1	LM78L05ACM	IC, REG, +5V 100 mA REGULATOR	U5
02-01523	9	1	LM78L12ACM	IC, REG, +12V 100 mA REGULATOR	U6
02-01523	10	1	L7809CD2T	IC, +9V, REG 1.5A TO-263	U7
02-01523	11	1	MMBT2907ALT1	TRANSISTOR, PNP, 2N2907A, SOT-23	Q1 Flip upside and bend legs toward the PCB
02-01523	12	1	IRL510	TRANSISTOR, N-CHANNEL HEX FET, TO220AB	Q2
02-01523	13	6	RLS4148TE11C	DIODE SMT, ROHM DIODE LL-34 SIG DIODE	D1-D6
02-01523	14	1	ERJ-3GSYJ332V	RES SMT, 3.3K OHM, 1/16W, 5%, 0603	R1
02-01523	15	1	ERJ-3GSYJ182V	RES SMT, 1.8K OHM, 1/16W, 5%, 0603	R2
02-01523	16	5	ERJ-3GSYJ103V	RES SMT, 10K OHM, 1/16 W, 5%, 0603	R3, R6, R15, R16, R21
02-01523	17	1	ERJ-3GSYJ223V	RES SMT, 22K OHM, 5% 0603	R4
02-01523	18	1	ERJ-3GSYJ104V	RES SMT, 100K OHM 1/16W 5% TYPE 0603	R5
02-01523	19	1	ERJ-3GSYJ681V	RES SMT, 680 OHM 1/16W 5% 0603	R7
02-01523	20	3	ERJ-3GSYJ102V	RES SMT, 1K OHM 1/16W 5% 0603	R8-R10
02-01523	21	1	ERJ-3GSYJ303V	RES SMT, 30K OHM 1/16W 5% 0603	R11
02-01523	22	1	ERJ-3EKF7151V	RES SMT, 7.15K OHM 1/16W 1% 0603	R12
02-01523	23	1	MFR-25FRF 14K0	RES, 14K OHM 1/4W 1% MF	R13, connected from U2 pin 12 to top pad of R13
02-01523	24	2	RM73B1JT106J	RES SMT, 10M OHM 1/16W 5% 0603	R17, R20
02-01523	25	2	ERJ-3GSYJ100V	RES SMT, 10 OHM 1/16W 5% 0603	R18, R19
02-01523	26	1	EVM-7JSX30B13	RES SMT, POT, 1K OHM 3MM SEALED, 3 TT	VR1
02-01523	27	12	ECU- V1H104KBW	CAP SMT, 0.1uF 50V 10%, X7R CER 1206	C1, C2, C12, C13, C16-18, C23-C26, C29
02-01523	28	3	ECU-V1H220JCV	CAP SMT, 22 pF CERAMIC 5% 50V 0603 NPO	C3, C4, C28
02-01523	29	2	ECU- V1H102KBV	CAP SMT, 1000 pF 50V CERAMIC 10% 0603 X7R	C6, C11
02-01523	30	1	ECU-V1H271JCV	CAP SMT, 270 pF 50V CERAMIC 5% 0603 NPO	C7
02-01523	31	1	ECU- V1H152KBV	CAP SMT, 1500 pF 50V CERAMIC 10% 0603 X7R	C8
02-01523	32	1	GRM42- 6C0G471G500AL	CAP SMT, 470 pF 500V 2% 1206 C0G"	C9
02-01523	33	1	GRM42- 6C0G121J500AL	CAP SMT, 120 pF 500V 5% 1206 C0G"	C10
02-01523	34	2	ECU- V1H272KBV	CAP SMT, 2700PF 50V CERAMIC 10% 0603 XR7	C14, C15
02-01523	35	4	ECE-A1EU220	CAP, 22UF 25V RADIAL ELECTROLYTIC 20%	C19-C22

Assembly #	Line #	Qty	Part #	Part Description	Reference Designator
02-01523	36	1	GRM42- 6C0G100J500AL	CAP SMT, 10 pF 500V 5% 1206 C0G	C30
02-01523	37	1	GRM42- 6C0G220J500AL	CAP SMT, 22 pF 500V 5% 1206 C0G	C31 (AS NEEDED)
02-01523	38	2	43LS477	INDUCTOR, 0.47 µH	L1, L2
02-01523	39	1	MCX0001	X0001 OSCILLATOR, CUSTOM 13.560 MHz, PARALLEL MODE, 22 pF LOAD, HC49 CASE, 30 PPM	
02-01523	40	1	MDC-096	CONN, MINI-DIN, 6-PIN	P1
02-01523	41	1	KF22-E9S-NJ	CONN, D-SUB 9P RECPT RT ANGLE WITH JACK SCREWS	DB9
02-01523	42	1	08-00170	LABEL, MCRF355 READER FIRMWARE, 355READ.HEX, 1/25/99, U4	@ U4
02-01523	43	1	ERJ-3GSYJ511V	RES SMT, 510 OHM 1/16W 5% 0603	R14

#### 6.0 READER SOURCE CODE FOR THE PICmicro<sup>®</sup> MCU

;receiver.asm

; Processor: PIC16C558 operating at 13.56 MHz ; Ti= 295 nsec processor 16c558 #include "P16c558.inc" \_\_\_\_config h'3ff2' ;protection off,PWRT enabled,watchdog disabled,HS oscillator #define CARRY STATUS,0 #define \_ZERO STATUS,2 #define \_125KHZ PORTA,1 #define \_RS232TX PORTA, 2 #define \_RS232RX PORTA, 3 #define \_RS232 PORTA #define SIGNAL PORTB,4 invmask = h'2';..... ;Define variables and constants here-delay =h′20′ wait =h'21' acctime =h'22' ;accumulated sync interval sum--also used as halfbit interval threshold halfthr acctime ;halfbit interval threshold #define halfthr =acctime ;halfbit interval threshold recv\_csumhi =h'23' ;2 bytes for storing received checksum recv\_csumlo =h'24' =h'25' ;RS232 bit counter bitcnt cycle\_cnt =h'26' =h'27' ;threshold value between halfbit and fullbit intervals halfthr ptr1 =h'28' ;temporary FSR storage =h'29' ;temporary FSR storage ptr2 =h'2a' ;character to transmit over RS232 TXchar =h'2b' ;temporary storage temp =h'2c' ;used to strip the framing `0' bits from the rec'd data array shiftcnt =h'2d' ;storage area for next character to send letters charcnt =h'2e' =h'2f' ;the LSb stores the last rec'd bit--flip it by complementing f lastbit ;;;Note that s/w tests for MSb to detect end of area--be careful if move to different ;;;processor or relocate this storage area recybits =h'40' ;32 bytes set aside for storing the received bits--actual number of bytes ; in transmission is 18 ;;Note that main loop uses bit tests to determine bit receive or runaway condition (to limit ;;processing time). Keep this in mind if recvbits storage area changed in the future. ;;40h-60h is reserved for received bits--actual bit receiving area 40h-51h, rest is overrun area ;;52h-73h set aside for ASCII conversion of received bytes before RS232 transmission. Note that ;;52h-60h contains no useful information from the use during receive of demodulated bits. Also, bits are not being received while the ASCII conversion and serial transmission are ;; ;; taking place. 'G' 1st character: "go" ;; Character 2-37: ASCII representation of received 18 bytes (until checksum used) ;; ;; Character 38: `\n' newline sendascii =h'52' ; begin of storage area for ASCII conversion of received bytes =d'14' ; defines number of received bytes to convert to ASCII & transmit xfercnt ;.....

; ;Overa ;	all function- To recover Manchester encoded RFID message after AM demodulation and comparator decision. The comparator input trips the interrupt on PORTB change.
;The :	steps are:
;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;	<ol> <li>Initialize registers to seek synch field.</li> <li>Determine bit width from synch field by averaging the periods between transitions over the synch field. TMRO is cleared at each edge. If the timer overflows before the next edge, synch seek starts over. The synch field is composed of 9 bits.</li> <li>Use the measured bit width to establish a threshold period between repeat bits and complement of previous bit. This is due to the Manchester encoding method. Since there is always a transition in the middle of each bit interval transmitted, a repeated bit will appear as a pair of edges that occur with a halfbit interval period. A bit that is the complement of the last received bit will appear as an interval between edges of a full bit interval period.</li> <li>Shift in bits as they are received into the storage array. When the timer overflows, consider the data field over. The received data format is MSb to LSb, where the MSb is the first bit received.</li> <li>There are 16 bytes in the message, followed by a 16 bit checksum of the message contents. The remaining bit is unused.</li> <li>Compute the checksum of the received 16 byte message and compare to the received</li> </ol>
;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;	<pre>checksum. 7- If checksums match, convert the message and the checksum into ASCII form and transmit over the RS232 serial link. The message format is:</pre>
;====; ;;isr	<pre>org h'000' ;RESET vector location goto init org h'004' ;interrupt vector location (): interrupt service routine interrupt service routine</pre>
; ; ;	interrupts enabled for transition on PORTB 1- BEWARE! To minimize interrupt response time, the w & status register are NOT
;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;	<ul> <li>archived.</li> <li>2- The isr execution path is determined by w register and uses calculated goto's. The w for next isr is set at end of current isr execution and is dependent on signal context (i.e. sync start, w/in sync, w/in data, etc.)</li> <li>Be very cautious heremust stay w/in 255 instructions for this to work!</li> <li>3- Sync field processed as follows:</li> </ul>
;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;	<ul> <li>-Ignore the first 4 transitions, they may be in response to tag power on reset</li> <li>-Accumulate the sum of next 8 intervals</li> <li>-Establish half bit width from full bit width threshold value based on average interval measured above. Due to Manchester encoding, repeat of previous bit will be a series of 2 halfbit width intervals, complement of previous bit will be a fullbit width interval. halfbit defined as 1.5x(average sync).</li> <li>-wait for interval over the fullbit threshold. This is end of sync. In accordance w/ Manchester encoding, the sync field will be: 1 1 1 1 1 1 1 0</li> </ul>
;==== isr ;firs	<pre>addwf PCL,f ;4 calculated goto t sync edge is calculated goto here clrf TMR0 ;5 movf PORTB,f ;6 must read PORTB before clearing RBIF bcf INTCON,RBIF;7 just in case timer interrupt happened just at 1st edge bcf INTCON,TOIF;8 movlw (first_cycle - isr-d'1');9 next isr calculated goto offset clrf lastbit ;10 lastbit @ end of sync = 0 reatfine ;12</pre>
;end (	of first cycle here. Note that first 4 transitions are ignored, because sync start is

; corrupted by tag power on reset. first\_cycle clrf TMR0 ;5 PORTB, f ;6 must read PORTB before clearing RBIF movf bcf INTCON, RBIF ;7 movlw (second\_cycle - isr-d'1') ;8 next isr calculated goto offset ;10 retfie ;end of 2nd cycle here. Note that first 4 transitions are ignored, because sync start is ; corrupted by tag power on reset. second\_cycle ;5 clrf TMR0 movf PORTB,f ;6 must read PORTB before clearing RBIF bcf INTCON, RBIF ;7 movlw recvbits ;8 movwf FSR ;9 set up to store data bits movlw (third\_cycle - isr-d'1') ;10 next isr calculated goto offset ;12 retfie ;end of 3rd cycle here. Note that first 4 transitions are ignored, because sync start is ; corrupted by tag power on reset. The 3rd cycle is the 4th transition, so from here we measure ;the longest interval in sync field. third cycle clrf TMR0 ;5 movf PORTB,f ;6 must read PORTB before clearing RBIF bcf INTCON, RBIF ;7 clrf acctime ;8 reset accumulated sync interval for average movlw (fourth\_cycle - isr-d'1') ;9 next isr calculated goto offset retfie ;11 ;end of 4th cycle here. Start looking for longest sync interval here. fourth\_cycle movf TMR0,w ;5 ;6 clrf TMR0 movf PORTB,f ;7 bcf INTCON, RBIF ;8 addwf acctime,f ;9 first measured sync cycle, must be the largest movlw (fifth\_cycle - isr-d'1') ;10 retfie ;12 ;end of 5th cycle here. fifth\_cycle movf TMR0,w ;5 ;6 clrf TMR0 movf PORTB,f ;7 INTCON, RBIF ;8 bcf addwf acctime,f ;9 acctime = acctime + TMR0 movlw (sixth\_cycle - isr-d'1') ;10 retfie ;12 ;end of 6th cycle here. sixth cycle movf TMR0,w ;5 movf PORTB,f :7 bcf INTCON, RBIF ;8 addwf acctime,f ;9 acctime = acctime + TMR0 movlw (seventh\_cycle - isr-d'1') ;10 retfie ;12 ;end of 7th cycle here. seventh cycle movf TMR0,w ;5 clrf TMR0 ;6 movf PORTB,f ;7 INTCON, RBIF ;8 bcf addwf acctime,f ;9 acctime = acctime + TMR0 movlw (eighth\_cycle - isr-d'1') ;10 retfie ;12 ;end of 8th cycle here. eighth\_cycle movf TMR0,w ;5

```
clrf TMR0
                       ;6
     movf PORTB,f
                      ;7
     bcf
            INTCON, RBIF ;8
     addwf acctime,f ;9
                           acctime = acctime + TMR0
     movlw (nineth_cycle - isr-d'1') ;10
     retfie
                      ;12
;end of 9th cycle here.
nineth cycle
     movf TMR0,w
                      ;5
                      ;6
     clrf TMR0
     movf PORTB,f
                      ;7
     bcf
           INTCON, RBIF ;8
     addwf acctime,f ;9
                            acctime = acctime + TMR0
     movlw (tenth_cycle - isr-d'1') ;10
     retfie
                      ;12
;end of 10th cycle here.
tenth_cycle
     movf TMR0,w
                      ;5
     clrf TMR0
                      ;6
     movf PORTB,f
                      ;7
     bcf
           INTCON, RBIF ;8
     addwf acctime,f ;9
                           acctime = acctime + TMR0
     movlw (eleventh_cycle - isr-d'1') ;10
     retfie
                      ;12
;end of 11th cycle here. --this is last of sync cycles to be accumulated. Average the result
;and determine halfbit threshold in remaining sync cycles.
eleventh cvcle
     movf TMR0,w
                      ;5
     clrf TMR0
                      ;6
     movf PORTB,f
                      ;7
           INTCON, RBIF ;8
     bcf
     addwf acctime,f ;9
                            acctime = acctime + TMR0
     movlw (twelfth_cycle - isr-d'1') ;10
     retfie
                       ;12
;end of 12th cycle here. Start averaging the sync interval accumulated time
twelfth_cycle
     movf PORTB.f
                      ;5
         INTCON, RBIF ;6
     bcf
     rrf acctime, f ;7 acctime/2
     rrf acctime,f ;8 acctime/4
           acctime,f ;9 avg interval = acctime/8
     rrf
     movlw h'lf'
                       ;10
                            clear 3 MSbs that may have been set by carry
     andwf acctime,f
                       ;11
           (cycle13 - isr-d'1') ;12
     movlw
     retfie
                       ;14
;end of 13th cycle here. Calculate the halfbit threshold = 1.5(sync interval avg) Note that
;that the threshold value will be kept in acctime (=halfthr)
cvcle13
     clrf TMR0
                      ;5
     movf PORTB,f ;6
     bcf
           INTCON RBIE ;7
           acctime,w ;8 half the sync interval avg
     rrf
                       ;9 halfthr = 1+1.5x(sync interval avg)
     addwf acctime,f
     incf
            acctime,f
                      ;10
     movlw (sync_end - h'100'-h'1'-isr) ;11
     bsf PCLATH,0 ;12 adjust for origin @ 100h
     retfie
                       ;14
     org h'100'
;sync end wait. End of sync is distinguished by a fullbit interval. ( T > halfthr )
sync_end
     movf TMR0,w
                       ;5
     clrf TMR0
                       ;6
     movf PORTB, f
                       ;7
          INTCON, RBIF ;8
     bcf
     subwf halfthr,w
                       ;9
                             Test interval to detect end of sync field (halfthr - w)
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```
movlw (sync_end - h'100'-isr-d'1') ;10
     btfss STATUS,C ;12 Carry set for halfthr >= w
     movlw (bit1 - h'100'-isr-h'1');12 If T > halfbit, end of sync detected. Proceed to data
processing
     retfie
                       ;14
;rec'd bit processing here --bit1 is 1st bit of 8 bit block
bit1
     movf TMR0,w
                       ;5
     clrf TMR0
                      ;6
     movf PORTB,f
                       ;7
     bcf INTCON, RBIF ;8
     subwf halfthr,w ;9
                           Test interval to determine bit. C = 1 for repeated bit
     btfsc STATUS,C
                       ;11
     goto halfabit1
                       ;12
;fullbit processing here
     comf lastbit,f ;12 Complement lastbit for fullbit measurement
     rrf lastbit,w
                     ;13
     rlf INDF,f
                      ;14 shift in the new bit
     movlw (bit2 - h'100'-isr-h'1') ;15
     retfie
                       ;17
halfabit1
;repeated bit (1 of 8)
         lastbit,w
     rrf
                       ;13
     rlf
           INDF, f
                       ;14
     movlw (half21-h'100'-isr-h'1') ;15
     retfie
                       ;17
;2nd half of bit interval processing
half21
           ;2nd half, bit1
     clrf TMR0
                    ;5
     movf PORTB,f
                       ;6
     bcf INTCON, RBIF ;7
     movlw (bit2-h'100'-isr-h'1');8
     retfie
                       ;10
;rec'd bit processing here --bit2 is 2nd bit of 8 bit block
bit2
     movf TMR0,w
                       ;5
     clrf TMR0
                       ;6
     movf PORTB,f
                       ;7
     bcf INTCON, RBIF ;8
     subwf halfthr,w ;9
                            Test interval to determine bit. C = 1 for repeated bit
     btfsc STATUS,C
                       ;11
     goto halfabit2
                       ;12
;fullbit processing here
     comf lastbit,f ;12 Complement lastbit for fullbit measurement
     rrf lastbit,w ;13
     rlf INDF,f
                      ;14 shift in the new bit
     movlw (bit3 - h'100'-isr-h'1') ;15
     retfie
                       ;17
halfabit2
;repeated bit (2 of 8)
     rrf
         lastbit,w
                       ;13
           INDF, f
     rlf
                       ;14
     movlw (half22-h'100'-isr-h'1') ;15
     retfie
                       ;17
;2nd half of bit interval processing
half22
           ;2nd half, bit2
     clrf TMR0 ;5
                      ;6
     movf PORTB,f
     bcf INTCON, RBIF ;7
     movlw (bit3-h'100'-isr-h'1');8
     retfie
                       ;10
;rec'd bit processing here --bit3 is 3rd bit of 8 bit block
bit3
     movf TMR0,w
                       ;5
     clrf TMR0
                       ;6
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```
movf PORTB,f
                       ;7
     bcf INTCON, RBIF ;8
     subwf halfthr,w ;9
                            Test interval to determine bit. C = 1 for repeated bit
     btfsc STATUS,C
                       ;11
     goto halfabit3
                       ;12
;fullbit processing here
     comf lastbit,f ;12 Complement lastbit for fullbit measurement
          lastbit,w
                     ;13
     rrf
     rlf INDF.f
                      ;14 shift in the new bit
     movlw (bit4 - h'100'-isr-h'1') ;15
     retfie
                      ;17
halfabit3
;repeated bit (3 of 8)
     rrf
          lastbit,w
                       ;13
     rlf
          INDF, f
                      ;14
     movlw (half23-h'100'-isr-h'1') ;15
     retfie
                      ;17
;2nd half of bit interval processing
half23
           ;2nd half, bit3
     clrf TMR0
                    ;5
     movf PORTB,f
                      ;6
     bcf INTCON, RBIF ;7
     movlw (bit4-h'100'-isr-h'1');8
     retfie
                       ;10
;rec'd bit processing here --bit4 is 4th bit of 8 bit block
bit4
     movf TMR0,w
                      ;5
     clrf TMR0
                      ;6
     movf PORTB,f
                      ;7
     bcf INTCON, RBIF ;8
     subwf halfthr,w ;9
                           Test interval to determine bit. C = 1 for repeated bit
     btfsc STATUS,C
                      ;11
     goto halfabit4
                      ;12
;fullbit processing here
     comf lastbit,f ;12 Complement lastbit for fullbit measurement
     rrf lastbit,w
                       ;13
     rlf INDF,f
                     ;14 shift in the new bit
     movlw (bit5 - h'100'-isr-h'1') ;15
     retfie
                       ;17
halfabit4
;repeated bit (4 of 8)
     rrf
         lastbit,w
                       ;13
     rlf
          INDF, f
                       ;14
     movlw (half24-h'100'-isr-h'1') ;15
     retfie
                      ;17
;2nd half of bit interval processing
half24
          ;2nd half, bit4
     clrf TMR0
                      ;5
     movf PORTB,f
                      ;6
     bcf INTCON, RBIF ;7
     movlw (bit5-h'100'-isr-h'1');8
     retfie
                      ;10
;rec'd bit processing here --bit5 is 5th bit of 8 bit block
bit5
     movf TMR0,w
                      ;5
     clrf TMR0
                       ;6
     movf PORTB,f
                      ;7
     bcf INTCON, RBIF ;8
     subwf halfthr,w ;9
                            Test interval to determine bit. C = 1 for repeated bit
     btfsc STATUS,C
                      ;11
                      ;12
     qoto halfabit5
;fullbit processing here
     comf lastbit,f
                      ;12 Complement lastbit for fullbit measurement
     rrf
           lastbit,w
                      ;13
     rlf INDF,f
                      ;14 shift in the new bit
     movlw (bit6 - h'100'-isr-h'1') ;15
```

retfie ;17 halfabit5 ;repeated bit (5 of 8) rrf lastbit,w ;13 rlf INDF, f ;14 movlw (half25-h'100'-isr-h'1') ;15 ;17 retfie ;2nd half of bit interval processing half25 ;2nd half, bit5 clrf TMR0 ;5 ;6 movf PORTB,f bcf INTCON, RBIF ;7 movlw (bit6-h'100'-isr-h'1') ;8 retfie ;10 ;rec'd bit processing here --bit6 is 6th bit of 8 bit block bit6 movf TMR0,w ;5 clrf TMR0 ;6 movf PORTB,f ;7 bcf INTCON, RBIF ;8 subwf halfthr,w ;9 Test interval to determine bit. C = 1 for repeated bit btfsc STATUS,C ;11 goto halfabit6 ;12 ;fullbit processing here comf lastbit,f ;12 Complement lastbit for fullbit measurement rrf lastbit,w ;13 ;14 shift in the new bit rlf INDF,f movlw (bit7 - h'100'-isr-h'1') ;15 retfie ;17 halfabit6 ;repeated bit (6 of 8) rrf lastbit,w ;13 rlf INDF, f ;14 movlw (half26-h'100'-isr-h'1') ;15 retfie ;17 ;2nd half of bit interval processing half26 ;2nd half, bit6 clrf TMR0 ;5 movf PORTB,f ;6 bcf INTCON, RBIF ;7 movlw (bit7-h'100'-isr-h'1') ;8 ;10 retfie ;rec'd bit processing here --bit7 is 7th bit of 8 bit block bit7 movf TMR0,w ;5 clrf TMR0 ;6 movf PORTB,f ;7 bcf INTCON, RBIF ;8 subwf halfthr,w ;9 Test interval to determine bit. C = 1 for repeated bit btfsc STATUS,C ;11 goto halfabit7 ;12 ;fullbit processing here comf lastbit,f ;12 Complement lastbit for fullbit measurement rrf lastbit,w ;13 rlf INDF,f ;14 shift in the new bit movlw (bit8 - h'100'-isr-h'1') ;15 retfie ;17 halfabit7 ;repeated bit (7 of 8) rrf lastbit,w ;13 rlf INDF, f ;14 movlw (half27-h'100'-isr-h'1') ;15 retfie ;17 ;2nd half of bit interval processing half27 ;2nd half, bit7

```
clrf TMR0
                      ;5
     movf PORTB,f
                      ;6
     bcf INTCON, RBIF ;7
     movlw (bit8-h'100'-isr-h'1') ;8
                       ;10
     retfie
;rec'd bit processing here --bit8 is 8th bit of 8 bit block
bit8
     movf TMR0,w
                       ;5
     clrf TMR0
                      ;6
     movf PORTB,f
                      ;7
     bcf INTCON, RBIF ;8
     subwf halfthr,w ;9
                           Test interval to determine bit. C = 1 for repeated bit
     btfsc STATUS,C
                       ;11
     goto halfabit8
                       ;12
;fullbit processing here
     comf lastbit,f ;12 Complement lastbit for fullbit measurement
     rrf lastbit,w
                     ;13
     rlf INDF,f
                      ;14 shift in the new bit
     movlw (bit1 - h'100'-isr-h'1') ;15
     incf FSR,f
                      ;16
     retfie
                       ;18
halfabit8
;repeated bit (8 of 8)
          lastbit,w
     rrf
                       ;13
          INDF, f
     rlf
                       ;14
     movlw (half28-h'100'-isr-h'1') ;15
     retfie
                ;17
;2nd half of bit interval processing
          ;2nd half, bit8
half28
                     ;5
     clrf TMR0
     movf PORTB,f
                       ;6
     bcf INTCON, RBIF ;7
     movlw (bit1-h'100'-isr-h'1') ;8
     incf FSR,f
                    ;9
                            advance to next byte in recvbits storage array
     retfie
                       ;11
;The negative RS232 supply is generated by an inverter clocked at ~125 KHz by port pin RA1.
       ;first pump up the -5V, i.e. generate 125 KHz clock (T=8 usec, ~27 Ti)
       ;run for a total of 128 cycles before sending data
      ;put line at stop bit level
alphabet
       clrwdt
     bcf INTCON,GIE ;make sure interrupts are off
     movlw sendascii
     movwf FSR
     movlw xfercnt ;# of ASCII represented received bytes to xfer
     addlw xfercnt
                      ;x2
     addlw h'3'
                     ;plus 2 start character "G" and newline character at end
     movwf charcnt
;;set up registers in bank 1
       bsf STATUS, RP0 ; point to bank 1
       movlw h'8'
       movwf TRISA
                         ;RA3 input, RA2-0 output
       movlw h'10'
       movwf TRISB
                         ;RB7-5,3-0 output, RB4 input
       movlw b'00001100' ;set up timer option for internal clock, prescale-->watchdog/16
       movwf OPTION_REG ;port B pullups enabled
       bcf
              STATUS, RP0 ; point back to bank 0
;;done setting up registers in bank 1, back to bank 0
              _RS232TX ;default is mark mode
       bsf
       call gen125khz
```

;start the test transmission sendA movf INDF,w TXchar movwf movlw d'8' movwf bitcnt ;stop bit last bsf \_RS232TX call TX\_RS232 ;stop bit = 3Ti call ti17 ; burn 17Ti (includes the 2Ti for the call) ;start bit first bcf \_RS232TX call TX\_RS232 ; burn 17Ti (includes the 2Ti for the call, adjusts the bit timing) call ti17 sendchar btfsc TXchar,0 ;1Ti goto setbit ;3Ti bcf \_RS232TX goto nextbit setbit bsf \_RS232TX ;4Ti nextbit call TX\_RS232 ;6Ti TXchar,f rrf ;7Ti call ti10 ;17Ti decfsz bitcnt,f ;18Ti ;20Ti goto sendchar ;stop bit last \_RS232TX bsf TX\_RS232 ;stop bit = 3Ti call incf FSR,f ;1 decfsz charcnt,f ;2 goto inalpha ;4 movlw d'255' movwf charcnt movlw d'10' movwf bitcht waiting call ti17 decfsz charcnt,f goto waiting decfsz bitcnt,f goto waiting goto seekinit inalpha call ti10 goto sendA ;; ;;subroutine--RS232 bit timing & 125 KHz voltage inverter maintenance ;; baud rate set to 9600 bps--this is a bit time of 104 usec ;; Timing for this subroutine: to104 loop is 5.605 usec, additional setup ;; overhead is 1.77 usec. If do 17 to104 loops, ;; that leaves 5.844 usec to make up in the calling routine to meet 104 usec target. 5.844= 19.8 Ti ;; ;; (20 Ti) ;; Note that 5.844 is not evenly divisible by the ;; instruction cycle time. Need to save one instruction every 5th bit sent--w/ the stop & start ;; ;; bit overhead, easier to save 2 extra instructions

```
;;
                          every character sent (10 bits)
*****
;;;
TX_RS232
    movlw d'17'
              ;time out 104 usec, Ti=295 nsec
    movwf wait
to104
    movlw invmask ;flip voltage inverter bit
    xorwf _RS232,f
     movlw d'4'
    movwf delay
wait4usec
    decfsz delay,f
                ;4 usec is half inverter clock period
     goto wait4usec
     decfsz wait,f
     goto to104
    movlw invmask
    xorwf _RS232,f
     nop
     nop
     nop
     return
;;
;;subroutine--generates 128 cycles at ~125 KHz for the RS232 voltage inverter
gen125khz
    movlw d'128'
    movwf cycle_cnt
next125
    bsf
         _125KHZ
    movlw d'4'
    movwf delay
highside
    decfsz delay,f
    goto highside
         _125KHZ
    bcf
    movlw d'4'
    movwf delay
lowside
    decfsz delay,f
     goto lowside
    decfsz cycle_cnt,f
    goto next125
    return
;;end gen125khz
*****
;
;;subroutine-til7: burn 17 Ti--includes the 2Ti to call this subroutine
;;
       ti15: burn 15 Ti, including call
       til0: burn 10 Ti, including call
;;
ti17
    movlw d'3'
               ;1
     movwf delay
               ; 2
burn9
     decfsz delay,f
               ;11
     goto burn9
     clrwdt
               ;12
```

;13 nop return ;15+2 for call ti17=17Ti ti15 movlw d'3' ;1 movwf delay ; 2 burn9Ti decfsz delay,f goto burn9Ti ;11 return ;13+2 for call ti15=15Ti til2 nop clrwdt ti10 dly1 ;2Ti goto dly1 qoto dly2 ;4Ti dly2 goto leaveti10;6Ti leaveti10 ;8Ti+2Ti=10Ti return ;;initialization init ; lst set up the I/O configuration--note that setting PORTB 7,6,5,4,0 as outputs disables ;them as external interrupt sources. In this application PORTB-4 is utilized as an ;external interrupt source upon change of state. All other external interrupt sources are ;set as outputs to disable them as interrupts. ;;set up registers in bank 1 bsf STATUS,RP0 ;point to bank 1 movlw h'8' movwf TRISA ;RA3 input, RA2-0 output movlw h'10' ;RB7-5,3-0 output, RB4 input movwf TRISB movlw b'00001000' ;set up timer option for internal clock, no prescaler movwf OPTION\_REG ;port B pullups enabled STATUS, RPO ;point back to bank 0 bcf ;;done setting up registers in bank 1, back to bank 0 movlw HIGH isr movwf PCLATH ;setup for calculated goto's dependent on context when entering ;isr ;;initialization for sync field search- done @ turn on & after data recovery complete (or failed) ;\_\_\_\_\_ seekinit clrwdt movlw d'19' movwf bitcnt ;clear the bit storage field movlw recybits movwf FSR clrbits clrf INDF incf FSR,f decfsz bitcnt,f goto clrbits movlw recvbits movwf FSR ;start of the received bits field movf PORTB,w ;read PORTB before clearing INTCON to be sure RBIF=0

clrf INTCON clrf TMR0 ; From here on, the w register represents the PCL offset when answering the isr. ; It is to be used for no other purpose until interrupts are disabled. ;\_\_\_\_\_\_ movlw d'0' clrf PCLATH bsf INTCON, RBIE ; enable portB change interrupt enable bsf INTCON,GIE ;global interrupts are now enabled. ;;tag word search ;The main loop monitors the TOIF flag to detect successfully received word (subject to ;checksum test). Tag word processing is isr driven. A calculated goto method is used for ;position context in tag word for speed. FOR THIS REASON, THE W REGISTER CANNOT BE USED ;BY THE MAIN LOOP! If the main loop detects a timer overflow, the w register is cleared to ;return processing to first sync edge search. ;Also, expect recvbits area to be @ 40h-52h while receiving data. The ptr will be tested to ;determine this bitwise (because w can't be used in the main loop). seeksync bcf INTCON, RBIE d′0′ movlw ; calculated goto offset for 1st sync edge processing clrf PCLATH clrf FSR ;FSR = 0 to indicate not gathering bits INTCON, RBIE bsf bcf INTCON, TOIF main clrwdt. btfsc FSR,6 qoto datamain ;receiving data, monitor progress INTCON,TOIF btfsc seeksync ; if TMR0 overflows w/o receiving bits, seeksync qoto goto main ; check for done receiving bits using TMR0 overflow as indicator. Also test for overflow from ;proper bit storage area for runaway condition (non tag noise tripping comparator) datamain clrwdt btfsc INTCON,TOIF calc\_checksum ; if timer overflows, calculate checksum of received data aoto ; if bit 5 set, FSR > 5fh and has overrun its proper area. btfsc FSR,5 goto seeksync ;search for sync. qoto datamain ;Data received at this point. Two processing tasks remain: ;1- the framing '0' bits must be removed from the received 14 data bytes and 16 bit checksum ;2- the checksum of the 14 data bytes must be calculated and compared to the received ; 16 bit checksum ; If checksums match, transmit data over RS232 link. calc\_checksum clrf INTCON clrqie INTCON.GIE bcf btfsc INTCON,GIE ;make sure it's clear before proceeding goto clrqie PORTB, f movf ; disable all interrupts while processing received data clrf INTCON ;remove the framing '0' bits by bit shifting the data array left until all framing 0s are ;shifted out movlw d'17' movwf bitcnt movwf shiftcnt

shiftout movlw recvbits+d'17' movwf FSR roll\_left rlf INDF, f decf FSR,f decfsz shiftcnt,f roll\_left ;rotate left shiftcnt # of bytes qoto decfsz bitcnt,f goto next\_RL goto framestripped ; bit shift left through the array (successively 1 byte less each time) next\_RL movf bitcnt,w movwf shiftcnt goto shiftout framestripped ;1st check for all 0s in data--This is an illegal combination movlw recvbits movwf FSR movlw d'14' movwf bitcnt zerotest movf INDF,w btfss STATUS,Z goto nonzero decfsz bitcnt,f goto zerotest goto seekinit ;all zeros received. Ignore the message nonzero ; do 16 bit checksum of first 14 bytes received. It should match the last 2 bytes received. movlw recybits movwf FSR movlw d'14' movwf bitcnt clrf recv csumlo clrf recv\_csumhi sumbytes movf INDF,w addwf recv\_csumlo,f btfsc STATUS,C incf recv\_csumhi,f ;carry into high byte as necessary incf FSR,f ;point to next data byte decfsz bitcnt,f qoto sumbvtes ;now compare the received checksum w/ the calculated checksum. Transmit data if they match. movf recv\_csumhi,w subwf INDF,f btfss STATUS,Z got.o seekinit ;point to received checksum LSB incf FSR,f movf recv\_csumlo,w subwf INDF,f btfss STATUS,Z qoto seekinit ;message passes checksum. Convert to ASCII and transmit. ;now convert to ASCII form movlw recvbits ;keep track of where in conversion movwf ptr1 sendascii movlw movwf ptr2 movwf FSR "G" movlw INDF movwf incf ptr2,f

	incf	FSR,f	
	movwf	INDF	;double "G" to indicate start
	incf	ptr2,f	;next ascii character
	movlw	xfercnt	;how many bytes to convert to ASCII
	movwf	bitcnt	
	movlw	h′4′	
	movwf	PCLATH	;set up PCLATH for lookup table
asciid	conv		
	movf	ptr1,w	
	movwf	FSR	
	swapf	INDF,w	
	andlw	h′f′	;isolate the MSN
	call	hex2asci	i
	movwf	temp	;hold the ASCII character
	movf	ptr2,w	
	movwf	FSR	
	movf	temp,w	<pre>istore ASCII representation of received byte MSN</pre>
	movwf	INDF	
	incf	ptr2,f	;advance ASCII ptr
	movf	ptr1,w	;back to received bytes
	movwf	FSR	
	movf	INDF,w	
	andlw	h′f′	;isolate the LSN
	call	hex2asci	i
	movwf	temp	
	movf	ptr2,w	
	movwf	FSR	
	moví	temp,w	store ASCII representation of received byte LSN;
	movwi	INDF	
	inct	ptr2,f	advance ASCII ptr
	inci	ptrl,I	advance received byte ptr
	decisz	bitcht,I	
. 1	goto	asciicor	V
;done	data con	version,	now indicate newline before sending
	moviw im af	" \n"	, newline character
	inci	FSR,I	
	MOVWL	INDF	
;clear	red for R	5232 trai	asmission
/ CICU	aoto	alphabet	
	9000	alphabee	
;hexad	decimal t	o ASCII d	conversion table
	orq	h'3ff'	
hex2as	scii		
	addwf	PCL, f	
	retlw	"0 <i>" ia</i>	scii O
	retlw	"1 <i>" i</i> a	scii 1
	retlw	"2 <i>"</i> ;a	scii 2
	retlw	"3 <i>"</i> ;a	scii 3
	retlw	"4" ;a	scii 4
	retlw	"5 <i>" ;</i> a	scii 5
	retlw	"6 <i>" ;a</i>	scii 6
	retlw	"7" ;a	scii 7
	retlw	``8″ ;a	scii 8
	retlw	"9 <i>" i</i> a	scii 9
	retlw	"A" ia	scii A
	retlw	"B" ia	scii B
		NOU :-	scii C
	retlw	10	
	retlw retlw	"D" ;a	scii D
	retlw retlw retlw	"D" ;a	scii D scii E
	retlw retlw retlw retlw	"D" ;a "E" ;a "F" ;a	scii D scii E scii F
	retlw retlw retlw retlw	"D" ;a "E" ;a "F" ;a	scii D scii E scii F
	retlw retlw retlw retlw end	"D" ;a "E" ;a "F" ;a	scii D scii E scii F

NOTES:
## МICROCHIP microID™ 13.56 MHz DESIGN GUIDE

## **Contact Programmer**

#### 1.0 INTRODUCTION

#### 1.1 Chapter Overview

This chapter will address the details of programming the MCRF355 device by using the MCRF355 Contact Programmer. All of the timing diagrams for the device test modes and other specifications can be found in the MCRF355/360 data sheet (DS21287) under Section 3.4, "Signal Timing." A detailed description of the test modes will not be included in this section. Please refer to the data sheet for more information.

Included in the DV103003 Development Kit is the MCRF355 Contact Programmer. This circuit offers one possible solution for programming the MCRF355 using a PIC16C63. The hardware details, firmware listing, and PC interface are provided here.

#### 1.2 Device Programming

The MCRF355 data array is made up of 154 EEPROM bits. These bits are directly accessed through the device test modes. When erased, each EE cell goes to logic '1'. A programming pulse width (Twc, as described in the data sheet) is required to bring each individual bit down to a logic '0'.

On the command side, three logic levels are required to program the device: VDD, VHH, VIH, VIL.

Vdd	2.5V
Vнн	20V typical
Vін	.7 * VDDT Min
VIL	.3 * VDDT Max

Section 3.0 in the data sheet is also titled "Device Programming." The information contained in this section can also be found there. The test mode commands that are required to program the MCRF355 are as follows:

#### Test Modes

- 1. Erase EE
- 2. Program EE
- 3. Read EE

The MCRF355 Contact Programmer is designed to carry out these test modes based on commands coming through the RS-232 communications port. The three voltage levels (VDD, VHH, VIH, VIL) are present on the programmer board, originating from the 24 VDC power supply. The test mode timings have been programmed into the PIC16C63, leaving a simple RS-232 command set to initiate and complete the required test modes.

#### 2.0 HARDWARE

#### 2.1 Description of Operation

Programming is initiated on the PC side. The MCRF355 Contact Programmer receives a command from the PC through the RS-232 port, and into the USART on the P16C63. Based on this command, the microcontroller then sends the proper test mode signal to the MCRF355 device, using the three voltage levels present on the programming board. Due to the high voltage level of VHH, additional circuitry was required to buffer these signals from the port pins of the PIC16C63. The switching of the three voltage levels is handled by the an analog switch. The complete schematic for the MCRF355 Contact Programmer can be found in the Section 5.0.

#### 3.0 FIRMWARE

#### 3.1 <u>Overview</u>

Control of the MCRF355 Contact Programmer is accomplished through simple ASCII commands. This enables the user to come up with a PC interface specific to his/her needs. The development kit includes RFLAB, a visual basic interface to the MCRF355 Contact Programmer. However, if a user interface is to be designed that uses the MCRF355 Contact Programmer board and existing firmware, operation of the firmware must be understood. It should be noted here that the MCRF355 Contact Programmer can easily be used in a number of different ways, depending on the operation of the firmware. The included schematic and BOM allows for this approach. This section outlines the operation of the firmware that is included with the development kit.

#### 3.1.1 COMMANDS

The simple ASCII commands mentioned above are described here:

TABLE 3-1: RS-232 COMMANDS, 9600 BAUD, N81

ASCII	Description
Р	Program device
E	Erase device
R	Read device
D	Receive data from PC
U	Upload data to PC

Any simple terminal program can be used to interface to the MCRF355 Programmer board. It should be understood that the PICmicro<sup>®</sup> programs the MCRF355 from data stored in RAM. Updating this data from the PC is accomplished through the serial commands. This data in RAM is described as the PICmicro data array. The commands are initiated with the above ASCII letter. A complete description of each command is included here:

#### • Program Device

An uppercase "P" initiates this command. This command programs the MCRF355 with the data that has been previously loaded into the PICmicro's data array. The busy light on the MCRF355 Contact Programmer board will go on, showing that programming has been initiated. Upon program completion, the light will go off, and an uppercase "Y" or an uppercase "N" will be echoed back to the PC. The letter "Y" corresponds to a successful program, the letter "N" indicates a failed program.

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#### Erase Device

An uppercase "E" initiates this command. The busy light on the MCRF355 Contact Programmer board will go on, showing that the erase command has been initiated. Upon completion of the erase, the light will go off, and an uppercase "Y" or an uppercase "N" will be echoed back to the PC. The letter "Y" corresponds to a successful erase, the letter "N" indicates a failed erase.

#### Read Device

An uppercase "R" initiates this command. The busy light on the MCRF355 Contact Programmer board will go on, showing that the read command has been initiated. This command updates the data array in the PIC16C65A with data from the MCRF355. Upon completion, the light will go off, and an uppercase "R" will be echoed back to the PC.

#### Receive Data

An uppercase "D" initiates this command. This command loads the PIC16C65A data array with the 154 data bits to be programmed. Following the uppercase "D," the PICmicro will expect 20 more bytes of data. the PICmicro will echo back after each byte. After the 20<sup>th</sup> byte, the busy light will go off, and the command is complete.

#### Upload Data

An uppercase "U" initiates this command. This command returns the 154 data bits from the data array in the PICmicro to the PC. Following the uppercase "U," a single space (ASCII 0x20) will initiate the data transfer. 20 bytes will follow. After the 20<sup>th</sup> byte, the busy light will go off, and the command is complete.

It should be noted here that the 154-bit data array is not evenly divisible by an 8-bit byte. The  $20^{th}$  data byte contains bits 152 and 153.



#### FIGURE 3-1: DATA BYTE 20

#### 3.1.2 COMMAND SEQUENCE

Using these five ASCII commands, the user is then able to program and verify the MCRF355 device. Using these five commands, the recommended command sequences follow:

#### Program

- 1. Erase the Device. Doing an erase command prior to programming is necessary to return all bits to the logic '1' state. Command "E."
- 2. Load the Data Array. The user must send the 20 bytes containing the 154 bits from the PC to the MCRF355 Programmer. Command "D."
- 3. Program the Device. The user must initiate programming. Command "P."

If an uppercase "Y" is returned, the device has been programmed.

#### 4.0 PC INTERFACE

#### 4.1 <u>Overview</u>

Included with the DV103003 developers kit is RFLAB 13.56, a Microsoft<sup>®</sup> Windows<sup>®</sup>-based program that handles the above described serial communication. This is a Visual Basic<sup>®</sup> interface that allows easy control of the MCRF355 Programming board. Figure 4-1 is a screen shot of this software, RFLAB 13.56.

#### 4.2 System Requirements

RFLAB is a 32-bit application developed using Visual Basic 5.0. It will only run under Windows 95 or higher.

#### 4.3 Installation

RFLAB 13.56 MHz comes on two 3.5-inch disks. The entire installation will require approximately 3 megabytes of space. Running a:/setup.exe on disk number 1 will install the software onto your Windows 95 or higher PC. After installation is complete, a shortcut to the executable can be found on your start menu. The default path for this shortcut is under <u>Program Files>RFLAB></u> <u>RFLAB 13.56 MHz</u>.

Rrogrammer	X
	LAB 13.56 MHz <sub>v1.0</sub>
Programmer Comman	ds Programming Options Tag
Clear Data	Automatic Post Increment     O     Microchip Format
Program	C Other
Erase	
Read	1 2 3 4 5 6 7 8 9 10 11 12 13 14
Data Word - (HEX)	11 12 13 AB C3 U5 1A 19 FE FF 3A 2A D3 76
Encoded HEX FF 84 42 4	5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 1 35 5B 0C 0A 1A 0C BF 9F E3 A1 53 4C EC 05 43 3F
DATA	* Note: Byte 20 contains 6 dummy bits (1's).
Progress:	Clear Log
RFLAB - 13.56 MHz Initiated Hardware detect running Programmer Found on Comm1.	
2/26/99 3:27 PM	Programmer Comm: 1 Reader Comm: X 🕂 Microchip

#### FIGURE 4-1: RFLAB 13.56 DIALOG

#### 4.4 <u>Operation</u>

#### **Detecting the Programmer**

In order for the software to run, the MCRF355 Contact Programmer must be connected to the PC through an available COM port. Please have the programmer connected to the PC, and powered up before you initiate RFLAB. It is important that the 24 VDC power supply be used. When RFLAB comes up, it will scan all of the available serial ports, looking for the MCRF Contact Programmer. Once the programmer is found, the status bar at the bottom of the window will indicate this. If the programmer is not found, try selecting the COM port manually instead of relying on the auto detection process. Manual selection of the COM port can be done by choosing which COM port on the menu: Options>COM Port If this also fails, please verify that all power connections and serial port connections are secure. Once the software has detected that a programmer is connected to the computer, you are free to program a device.

#### 4.4.1 COMMAND BUTTONS

The top left corner of the window will show you four command buttons. Clear Data, Program, Erase, and Read. The CLEAR DATA button will clear the text boxes in the window. This command will not erase the device, it just clears the text boxes on your screen. The ERASE button will send the erase command to the programming board. The PROGRAM button will initiate the programming sequence described above in Section 3.1.2. A single click will Erase the device, download the data, program the device, and then verify the program. The READ button will send a Read command, followed by an Upload command to the programming board. The 20 text boxes on the screen will then be updated with the correct data. The bottom third of the programming window shows a list box. This list box will echo the commands as they are being sent to the MCRF355 Contact Programming board. All of the command buttons described will log activity in this box. This box is provided to better describe the ASCII commands behind the command buttons.

#### 4.4.2 DATA FORMAT

The top right corner of the programming window will show you a selector labeled TAG. The two selections are marked "Microchip" and "Other." This selector toggles the way the data is encoded into the 154-bit stream. When the selector is set to "Other," the user has complete control over each bit. The 20 test boxes labeled HEX DATA are free to be edited. When the selector is set to "Microchip," only 14 of the 20 data bytes are free for edit. An additional 14 text boxes will pop up showing this. This mode encodes these 14 data bytes into a 154 bit stream. Nine header bits, two checksum bytes, and framing zeros are encoded along with these 14 data bits. This encoding scheme is detailed in Figure 4-2. The "Microchip" format is used by firmware in the 13.56 MHz reference reader, included in the DV103003 kit.

#### FIGURE 4-2: MICROCHIP TAG FORMAT



#### 5.0 CONTACT PROGRAMMER SCHEMATIC



#### 6.0 CONTACT PROGRAMMER BILL OF MATERIALS

Assembly #	Qty	Part #	Manufacturer	Part Description	Reference Designator
02-01524	1	02-01524-D		PCB ASSY DWG, MCRF355 microID Programmer	
02-01524	1	03-01524		SCHEMATIC, MCRF355 microID Programmer	
02-01524	1	04-01524		PCB FABRICATION, MCRF355 microID Programmer	
02-01524	1	PIC16C63A-04/P	MICROCHIP	IC, PIC16C63A-04/SP, 8 BIT CMOS MICROCONTROLLER 28P	U5
02-01524	1	110-91-328-41-001	MILL-MAX	SOCKET, COLLET OPEN FRAME 28P .300W	xU5
02-01524	1	MC7805ACT	MOTOROLA	IC, +5V REG 0.5A	U2
02-01524	1	AC-001	POWER DYNAMICS	JACK, POWER, 3 PIN, PC MOUNT	J2
02-01524	1	521-9173	DIALIGHT	LED, GREEN T1-3/4 DIFFUSED	D3
02-01524	2	521-9174	DIALIGHT	LED, YELLOW T1-3/4 DIFFUSED	D1, D4
02-01524	1	OECS-100-1-A101A	ECS	XTAL OSC, 10.000 MHZ, 14P FULL SIZE	Y1
02-01524	1	MAX232ACPE	MAXIM	IC, HS 5V DUAL RS232 DRIVER 16 DIP	U1
02-01524	1	MCP130-450DI/TO	MICROCHIP	IC, TO 92, SUPERVISOR CIRCUIT W/OPEN DRAIN OUTPUT	U4
02-01524	1	KF22-E9S-NJ	KYCON	CONN, D-SUB 9P RECPT RT ANGLE WITH JACK SCREWS	J1
02-01524	1	2-0016-03340-000- 006-00X	3M TEXTOOL	SOCKET, TEST, 16P DIP (0.300) GREEN	xU3
02-01524	15	592CZ5U104M050B	SPRAGUE	CAP, CER AXIAL 0.1uF 50V	C1,C2,C4- C8,C10-C17
02-01524	6	470QBK	YAGEO	RES, 470 OHM 1/4W 5% CAR- BON FILM RES	R2-R7
02-01524	1	10QBK	YAGEO	RES, 10 OHM 1/4W 5% CAR- BON FILM RES	R1
02-01524	2	B3F-1000	OMRON	KEYSWITCH, MOMENTARY PCB MOUNT	SW1, SW2
02-01524	4	SJ-5018	3M	MISC, RUBBER FEET, .50 SQ .23 HIGH BLACK	Placed at corners of PCB
02-01524	1	08-00126		LABEL, NEED HELP WITH ASSY/SERIAL	
02-01524	1	08-00171		LABEL, MCRF355 PROGRAM- MER FIRMWARE, 355_9.HEX, x/xx/99, U1, CS: xxxxh	@ U1
02-01524	1	TSW-1-15-07-G-S	SAMTEC	HEADER, 1x15, BREAKAWAY, 0.025 SQ POST, GD CONTACT	TP1
02-01524	1	577202B00000	AAVID	HEATSINK, TO-220, 0.5	@U2
02-01524	1	P13		SCREW, #4-40 x 3/8 PANHEAD PHILLIPS	@U2

Assembly #	Qty	Part #	Manufacturer	Part Description	Reference Designator
02-01524	1	701-7357	CONCORD	NUT, #4-40 HEX STEEL CAD-PLATED	@U2
02-01524	1	ADG417BN	ANALOG DEVICES	IC, ADG417BN ANALOG SWITCH, 8P DIP	U8
02-01524	1	MAX518	MAXIM	IC, MAX518 8-BIT DAC, 8P DIP	U6
02-01524	1	OP295	ANALOG DEVICES	IC, OP295 DUAL OP AMP	U7
02-01524	1	521-9165	DIALIGHT	LED, RED T1-3/4 DIFFUSED	D2
02-01524	1	TSW-102-07-S-S	SAMTEC	HEADER, 2 PIN 0.025 SQ POST	JP1
02-01524	1	MNT-102-BK-T	SAMTEC	2 POSITION JUMPER BLOCK (SHUNT)	@JP1
02-01524	1	A470J15C0GHVVWA	PHILLIPS	CAP, 47pF AXIAL CERAMIC C0G 100V 5%	C9
02-01524	2	5043CX5K100J	PHILLIPS	RES, CF 5.1K 5% 1/4W	R10,R14
02-01524	1	MFR-25FBF 22K1	YAGEO	RES, 22.1K OHM 1/4W 1% METAL FILM RES	R8
02-01524	1	MFR-25FBF 2K21	YAGEO	RES, 2.21K OHM 1/4W 1% METAL FILM RES	R9

### 7.0 CONTACT PROGRAMMER SOURCE CODE FOR THE PICmicro<sup>®</sup> MCU

#include <P16c63.inc> ; include file for the processor

TITLE "MCRF355 Programmer Board" \_\_\_config b'00000001000001' ;protection off,PWRT disabled,watchdog disabled,XT oscilla-

tor

; Note: Assume 10 Mhz Crystal -=> 1 instruction = 400ns, .4us

list p=16c63

;The purpose of this firmware program is to accept commands via RS-232 and execute ;a set of commands on the MCRF355 (DUT). The device is serially programmed using ;the MCRF clock dutsck and data dutsda. The dut Vcc is generated by an 8-bit DAC ;through a unity gain buffering Op-Amp. The DUT programming voltage is also generated ;by an 8-bit DAC through a buffering Op-Amp with a gain of 11. An analog switch ;is used to isolate the Op-Amp Vpp from the dutsda line, as they are multiplexed. ;The program is structured to conduct read of FF after erasing. The program also ;goes directly to the read mode after programming. MCRF355 device serial test modes ;are used for erase, read, and program as follows:

;TEST MODE CODES FOR THE MCRF355 #define erase\_code b'11010100' #define read\_code b'11010110' #define prog\_code b'11010010'

;Serial Commands from PC - Send ERASE command to TAG ; Ε IJ - Upload data array to PC ; - Download data array from PC ; D - Send PROGRAM command to TAG P ; - Send READ command to TAG ; R \*\*\* any unknown command will result in an error condition, in which the PICmicro will ; return a lowercase 'e' to the PC and flash the busy light for 2 seconds. ; ;General program description: ; Five of the above commands/routines (Erase, Read, Program, Upload, and Download) can be used ; to program/erase/read the TAG. The Program / Read commands update the data\_arry in the picMicro. ; The following are examples of how one would erase/read/write to the TAG: ;Erase Sequence: ; 1.  $\ensuremath{\ensuremath{^{\circ}}\xspace E''}$  - Send the erase command to the PART ; 2. "R" - update the picMicro data\_array ;Read Sequence: ; 1. "R" - update the picMICRO data\_aray ; 2. "U" - upload this data array to the PC ; Program Sequence: (includes an erase, erase verify, and program verify) ; 1.  $\ensuremath{\ensuremath{^{\circ}}\xspace E''}$  - Send the erase command to the PART ; 2. "R" - update the picMicro data\_array ; 3. "D" - download data to be programmed ; 4. "P" - Program the TAG ; 5. "R" - Read back from the TAG ; 6. "U" - upload and verify all bits programmed.

;\* for multiple programs of a known blank part, the command/routine ``P'' is all that would be required.

;Definitions are as follows:

```
#define dutpgm
                               portb,0
                                          ; push-button programming
#define dutsck
                                          ; serial clock for dut
                               portb,2
#define serial_switchportb,3
                                          ; junper for serial programming
#define led_yellowportb,4
                                         ; BUSY indicator
#define led_red
                               portb,5
                                        ; Fail indicator
                              portb,6
#define led_green
                                        ; Pass indicator
#define dutsda
                                          ; serial data for clock
                              portb,7
#define sda
                               porta,0
                                          ; DAC serial data
#define scl
                               porta,1
                                          ; DAC serial clock
#define dutvpp
                                          porta,2; Analog Switch b enable for Vpp
#define which_dacflag,7
                                          ;This flag is used to select either
                                           ;DAC 0 or 1
#define current_bitflag,0
;These are 8-bit DAC, vref = 5.0V voltages going through op-amp stages
; whh has gain of 11X, vcc has gain of 1X
#define vil.0
                        ;will get you 0 volts
;Memory Allocation
;-----
                        cblock
                                   0x20
rcv_data ;UART data
read_byte;Storage location during read_device
temp
                       ;TEMP variable
                        ;Temp variable
temp1
                        ;TEMP variable
temp2
tempa
                        ;TEMP variable
tempb
                        ;TEMP variable
tempd1
                        ;TEMP variable
                        ;TEMP variable
tempd2
mcrf_bottom :20;bottom of the entire data spot
pc_bottom:20;bottom of the entire data spot, used for verify.
temp3
                       ;TEMP variable
ucount
                        ;TEMP variable
flag
                        ;TEMP variable
                        ;Vpp Programming voltage for DUT
vhh
                        ;Vcc voltage for DUT
vcc
daber1
                        ;TEMP variable
daber2
                        ;TEMP variable
Vdut
                        ;dut Vpp variable
                        endc
;
        flag
;-----
;7 - which DAC is being SET
;6
;5
;4
;3
; 2
;1
;0 - used for BIT toggling
```

; MAIN ROUTINE

;

RR		org goto	0 1	)x00 reset	;RE	ESET VECTOR	
		org	C	)x05	;Pro	rogram Memory Begin	
Set up	the Data	Direction R	egisters	Port 1	3		
reset	bsf	STATUS, RP0	;ba	nk1	-		
	clrf		PORTB			;Clear pins	
	movlw	в'0000001'	;				
	movwf	TRISB	;set	DDR-	port	tB	
	bcf		status,r	p0		i	
	clrf		PORTB			Clear pins	
;Set up	the Data	Direction R	egisters	Port A	A		
	bsf	STATUS, RPO	;ba	nk1			
	movlw	В'0000000'	;				
	movwf	TRISA	;set	DDR-	port	tB	
	bci		status,r	p0		;	
	clrī		PORTA			Clear pins	
;Set up	the UART						
	bsf		STATUS . R	P0		Select register page 1	
	movlw		b'001000	00'		;Enable RCIF interrupt	
	movwf		PIE1			·	
	movlw		.64			;9600 baud @10MHz	
	movwf		SPBRG				
	movlw		b'101001	00′		;Async, High baud rate	
	movwfTXS	ГА					
	bcf		STATUS, R	.P0		;Select register page 0	
	movlw		b'100100	00′		;Enable continous reception	
	movwf		RCSTA		;	8-bit,spen=1,cren=1 to enable rcv	
	movlw		b'010000	00′		;disable global interrupts	
	movwf		INTCON				
;Reset t	he DACs	to OV and ope	en the ar	nalog s	switc	cch	
	bsf	dutv	; qq	open a	nalo	og switch	
	bsf	flag	r,7;	DAC 1	to O	0V	
	movlw	vil					
	movwf	vdut					
	call	SetD	ACXV				
	bcf	flag	r,7 ;	DAC 0	to O	V0	
	movlw	vil					
	movwf	vdut					
	call	SetD	ACXV				
;Set up	variable	5					
	movlw	.98					
	movwf	vhh	;	Set Vh	nh to	.0 .98 in 8-bit DAC with gain of 11 $\sim$ 20	v
	movlw	.128					
	movwf	vcc	;	Set DU	JT VC	cc to 2.5V, 8-bit DAC with unity gain	

main

; This is the main loop. The PICmicro will sit here and ; wait for a byte to come in from the PC. wait bcf led\_yellow ;Turn off busy light waitloop btfss pirl,rcif;Check if a byte has come into UART goto waitloop ;has the pattern arrived yet? movf rcreg,0 ;move rcreg into w rcv\_data ;move w into rcv\_data movwf bcf led\_green bcf led\_red bsf led\_yellow ;Execute when data received in UART cchk1 0x50 ; `P' rcv\_data,0 ; exclusive OR against the command movlw 0x50 xorwf status,2 ; if ZERO bit is set, they were the same. btfss qoto cchk2 ; False call program\_device; True ; "Y" for true movlw 0x59 ; test for programming success btfss flag,1 movlw0X4E; "N" for falsemovwftxreg; ack command complete to pc goto wait novlw 0x45 ; `E' xorwf rcv\_data,0 ; exclusive OR against the command cchk2 movlw 0x45 status,2 ; if ZERO bit is set, they were the same. btfss goto chk3 ; False call erase\_device; True 0x59 ; "Y" for True movlw btfss flag,1 ; Test for Erase Success movlw0x4E; "N" for Falsemovwftxreg; ack command complete to pc goto wait novlw 0x52 ; `R'
xorwf rcv\_data,0 ; exclusive OR against the command chk3 movlw 0x52 btfss status,2 ; if ZERO bit is set, they were the same. qoto chk4 ; False call read\_device; True movlw 0x52 movwf txreg ; ack command complete to pc goto wait ; `U' chk4 movlw 0x55 xorwf rcv\_data,0 ; exclusive OR against the command status,2 ; if ZERO bit is set, they were the same. btfss goto chk5 ; False call upload ; True goto wait novlw 0x44 ; `D' xorwf rcv\_data,0 ; exclusive OR against the command chk5 movlw 0x44 status,2 ; if ZERO bit is set, they were the same. btfss qoto chk6 ; False

movlw 0x44 ; ack command complete to pc movwf txreg call download ; True goto wait ; " " space chk6  $0 \times 20$ movlw rcv\_data,0 xorwf btfss status,2 goto errr ; False movlw 0x53 movwf txreg ; ack command complete to pc wait qoto ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* ;\*program EEPROM\* ;\*\*\*\*\*\*\*\*\*\*\* ; Sends the program command sequence to the TAG ; and then program from the PICmicro's data array (mcrf\_bottom). ; 5/11/99 ; program\_device ;Give dut start bit Call dutStart movlw prog\_code ;load the proper opcode ;set the opcode to be sent movwf temp Call send\_opcode ;send the opcode movlw pc\_bottom movwf FSR movlw .20 ;20 bytes/word movwf temp llpm2 INDF,0 ;BYTE LOOP movf movwf temp2 movlw .8 ;8 bits/byte movwf tempb anotherbit btfss temp2,7 ;BIT LOOP Call pgm\_pulse rlf temp2,1 bsf dutsck ;send a clock to get it on the next bit call dly\_4uS bcf dutsck call dly\_4uS decfsz tempb,f ;all BITS finished? goto anotherbit ;No, goto bit look incf FSR,f decfsz temp,1 ;all BYTES finished? llpm2 ;No, goto byte loop goto Call dutSTOP ;Give dut stop bit

; \* \* \* \* \* \* \* \* \* \* \* \* \* \*

;\*Read EEPROM\*

; \* \* \* \* \* \* \* \* \* \* \* \* \* \*

; Sends the read command sequence to the TAG

; and then puts the data into the PICmicro's data array (mcrf\_bottom).

; 5/11/99

;

read\_device

read\_byteloop

Call	dutStart	;Give dut start bit
movlw	read_code	;load the proper opcode
movwf	temp	;set the opcode to be sent
Call	send_opcode	;send the opcode

;now READ in the data and put it into RAM (starting at location mcrf\_bottom)

bsf	STATUS, RPO	;bank1	
movlw	b'1000	)001′ ;!	
movwf	trisb		;switch port to an INPUT
bcf	STATUS, RPO	;bank0	
movlw	mcrf_b	ottom ;	
movwf	FSR		;set pointer to bottom of data Array
movlw	.20		;
movwf	temp		;number of bytes to the end
oyteloop		;BYI	E LOOP

dutSTOP

	movlw movwf movlw movwf	.8 tempb 0xFF temp2		;default data to all 1's
read_bitl	cop rlf call call decfsz goto	<pre>read_byte,1 read_one_bit clock_mcrf tempb,1 read_bitloop</pre>	;BIT LOOP ;Go and READ th ; ;ROLL THE BITS,	;First rotate is dummy he VPRG LINE ;FINISHED WITH BITS? , GOTO BIT LOOP
	movf movwf incf decfsz goto	<pre>read_byte,0 INDF FSR,f temp,1 read_byteloop</pre>	;NO, GOTO BYTE	;data to be put into pic memory ;FINISHED WITH BYTES? LOOP

;Give dut stop bit

;Verify

Call

;\*\*\*\*\*

	bsf	flag,1	;reset flag
	movlw	.19	; 20 byte word
	movwf	ucount	;
	movlw	MCRF_bottom	
	movwf	temp	; first counter
	movlw	PC_bottom	
	movwf	temp2	; second counter
topoloop			
	movf	temp,0	; get first place
	movwf	FSR	
	movf	INDF,0	; get first data

	movwf	daber1	; store first data
	movf	temp2.0	; get second place
	movwf	FSR	, gee become prace
	movf	INDF,0	; get second data
	movwf	daber2	; store second data
;now comp	pare the two dat	ta sets: daberl, an	d daber2
	incf	temp,1	;increase the two pointers
	incf	temp2,1	;increase the two pointers
	mort	dabari 0	
	NODME	daber1,0	
	htfee	status 2	
	goto	false	
	decfsz	ucount,1	
	goto	topoloop	
	goto	BITSTWO	
false			
	bcf	flag,1	
	bsi	led_red	;turn on fail led
	decisz	ucount,1	
	9010	соротоор	
;now comp	pare the final t	wo bits (byte 20)	
;temp and	d temp2 are ALRE	EADY on the 20th by	te
bitstwo			
	movf	temp,0	
	movwf	FSR	
	movf	INDF,0	
	movwi	daber1	
	movi	temp2,0	
	mout	FSR INDE 0	
	movruf	INDF,0 daber2	
	movlw	b'11000000' ;mask	off the bottom 6
	andwf	daber1.1	
	andwf	daber2,1	
	movf	daber1,0 ;now co	ompare
	XORWF	daber2,0	-
	btfss	status,2	
	goto	false2	
	btfsc	flag,1	; test for programming success
	bsf	led_green ;turn (	on pass led
	return		
false?			
LUIDCZ	bcf	flag,1	
	bsf	led red	;turn on fail led
	return		
	RETURN		
; Read an	nd Flag bit eith	ner 1 or 0	
read_one_	_bit		
	USI btfac	read_byte,U	
	baf	uutsua	
	return	reau_byte,0	
	recurii		

; \* \* \* \* \* \* \* \* \* \* \* \* \* \* ;\*Erase EEPROM\* ;\*\*\*\*\*\*\*\*\*\* ; Sends the erase command sequence to the TAG ; 5/11/99 erase\_device Call dutStart ;Give dut start bit movlw erase\_code ;load the proper opcode movwf ;set the opcode to be sent temp Call send\_opcode ;send the opcode Call pgm\_pulse Call dutSTOP ;Give dut stop bit

;adding the erase verify ;fill the obottom with 0xff

	movlw	.20
	movwf	ucount
	movlw	PC_bottom
	movwf	FSR
elp1		
	movlw	0xFF
	movwf	INDF
	incf	FSR,1
	decfsz	ucount,1
	goto	elp1
	goto	read_device

; \* \* \* \* \* \* \* \* \* \* \* \* \* \* \*

;program pulse routine ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* \*

pgm\_pulse

;

b	cf	dutvpp	Close Analog switch to dut Vpp
b m C	sf ovf ovwf all	flag,7 vhh,0 vdut SetDACXV	;Set Dac 1 to be set ;Set Vpp = 20V (gain of 10) ;Load the register ;Turn on the DAC
C	all	d10_10ms	
b m m	sf ovlw ovwf all	flag,7 vil vdut SetDACXV	;Set Dac 1 to be set ;Set Vpp = 0V ;Load the register ;Turn on the DAC
C	all sf	d10_1ms dutvpp	;Close Analog switch to dut Vpp
r	eturn		
******			

;sends a clock pulse with the vprg line at 0 volts ; Vil pulse (just clock) 

clock\_mcrf

bsf	dutsck	;clock pulse	
call	dly_4uS	;send a clock to ADVANCE to the next bit	
bcf	dutsck		
return			

dutStart

;rising edge of clock during a Vhh pulse

bsf	STATUS, RPO	;bank1	
movlw	B'1000001'	;TRI-state	e the READIN pin of port B
movwf	TRISB	;while	the START BIT is being
bcf	status,r	p0	;sent
;clrf	PORTB		;
bcf	flag 7		Set DAC $($ to be set (Dut Vcc)
movf	vcc.0		iSet Vcc = 2.5V
movwf	vdut		Move Vcc = 2.5 into variable
Call	SetDACXV		;SET the voltage on VCC
			2
bcf	dutvpp		;Close Analog switch to dut Vpp
bsf	flag,7		;Set Dac 1 to be set
movf	vhh,0		;Set Vpp = 20V (gain of 10)
movwf	vdut		;Load the register
Call	SetDACXV		;Turn on the DAC
call	d10 1mg		
call	d10_1ms		
Cull			
bsf	dutsck		
bsf	flag.7		
movlw	vil		
movwf	vdut		
call	SetDACXV		
call	d10_1ms		
call	d10_1ms		
bcf	dutsck		
bsf	dutvpp		;Open Analog switch to dut Vpp
call	d10_1ms		;
bcf	dutsda		;make sure dut data line is low
bsf	STATUS, RPO	;bank1	
movlw	b'000000	01′	71
movwf	trisb		;switch port to an OUTPUT
bcf	STATUS, RPO	;bank0	

return

#### dutStop

;Vhh pulse during clock high

bsf	STATUS, RPO	;bankl
movlw	B'1000001'	;TRI-state the READIN pin of port B
movwf	TRISB	;while the START BIT is being
bcf	status,r	p0 ;sent
;clrf	PORTB	;
bcf	dutvpp	;Close Analog switch to dut Vpp

bsf	dutsck		
bsf	flag,7		;Set Dac 1 to be set
movf	vhh,0		;Set Vpp = vhh
movwf	vdut		;Load the register
call	setDACXV		;Turn on the DAC
call	d10_1ms		
call	d10_1ms		
bsf movlw	flag,7 vil		;Set Dac 1 to be set ;Set Vpp = vil
movwf	vdut		;Load the register
call	setDACXV		;Turn on the DAC
call	d10_1ms		
call	d10_1ms		
bcf	dutsck		
bsf	dutvpp		;Open Analog switch to dut Vpp
bcf	dutsda		;make sure dut data line is low
bsf	STATUS, RPO	;bank1	
movlw	b'000000	01′	;!
movwf	trisb		;switch port to an OUTPUT
bcf	STATUS, RPO	;bank0	

return

send\_opcode

movlw	.8
movwf	tempb
CALL	dly_4uS
BSF	dutsck
CALL	dly_4uS
bcf	dutsck
CALL	dly_4uS
bsf	dutsda
CALL	dly_4uS
bsf	dutsck
CALL	dly_4uS
bcf	dutsck
CALL	dly_4uS
bcf	dutsda
CALL	dly_4uS

#### b2mloop

	bsf	flag,0
	btfss	temp,7
	bcf	flag,0
	Call	Sendbit2mcrf
	rlf	temp,1
	Decfsz	tempb,1
	goto	b2mloop
	Return	
Sendbit2m	crf	
	btfsc	flag,0

bsf dutsda CALL dly\_4uS bsf dutsck dly\_4uS CALL bcf dutsck CALL dly\_4uS bcf dutsda CALL dly\_4uS retlw 0 ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* ;\*UPLOAD to PC\* ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* ; Sends the data\_array to the PC. upload movlw .20 ; 20 byte word movwf ucount ; movlw mcrf\_bottom; FSR ; set pointer to bottom of array movwf call d10\_1ms ; uwait btfss pirl,rcif; ; waiting for inital handshake (Space) goto uwait d10\_1ms ; call movf INDF,0 ; txreg ; send the data movwf incf FSR,f ; increase pointer call d10\_1ms ; decfsz ucount,1; all bytes sent? uwait ; goto return ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* ;\*Download from PC\* ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* ; Fills the PICmicro data array with data from the PC download movlw .20 ; 20 BYTE WORD movwf ucount movlw pc\_bottom movwf FSR ; SET pointer to bottom of array btfss waitd pir1,rcif waitd ; has the pattern arrived yet? qoto movf RCREG,0 ; move rcreg into w movwf INDF txreg ; ack it back movwf incf FSR,f ; increase pointer decfsz ucount,1; ALL BYTES received? waitd ; NO, look again goto return errr ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* ;\*Error condition\* ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* ; Sends the 'e' back to the PC. This is ; also how RFLAB detects if there is a programmer ; connected on one of the COMM ports.

;blink th	ne light- someth	ning went wrong	
	movlw	0x65	;'e'
	movwf	txreg	; send it
	call	d10_10ms	
	movlw	.18	
	movwf	tempa	
		-	
flm	bsf	led_yellow	;flash the LED for ~2 seconds (visible error notifica-
tion to t	the user)		
	bsf	led_red	
	bsf	led_green	
	call	d10_10ms	
	call	 d10 10ms	
	call	d10 10ms	
	call	d10 10ms	
	call	d10 10ms	
	call	d10 10ms	
	call	d10 10ms	
	call	d10 10ms	
	call	d10 10ms	
	bof	led vellow	
	bcf	led red	
	bcf	led green	
	call	$d_{10}$ 10mg	
	call	d10_10mg	
	call	d10_10ms	
	call	d10_10mg	
	decfsz	tempa 1	
	goto	flm	
	goto		; back to waiting for another command
	9000	wait	/ back to waiting for another command
	return		
	goto	wait	
	9000	wart	
SetDACXV			
DCUDACAV	Call	DadStart	
	moulw	b(01011000)	
	movwf	temp1	
	call	byte2DAC	
	Call	Dytezdat	
	Call	Ack	
	Cull	ACA	
	moulw	b/0000000/	
	htfsa	flag 7	
	moulw	b ( 00000001 (	
	movruf	temp1	
	Call	byte2DAC	
	Call	Dytezdat	
	Coll	Ack	
	Call	ACA	
	movf	Vdut 0	: Change Vdut DACO = dut Vgg DAC1 - dut Von
	movrwf	temp1	, change vale, bace - all vee, bact - all vpp
	Call	byte2DAC	
	Call	DYLEZDAL	
	Call	Ack	
	Call	DacSton	
	Call	Dacocop	

#### Return

#### byte2DAC

	movlw	.8
	movwf	temp3
b2dloop		
	bsf	flag,0
	btfss	temp1,7
	bcf	flag,0
	Call	Sendbit2Dac
	rlf	temp1,1
	Decfsz	temp3,1
	goto	b2dloop
	Return	

#### Sendbit2Dac

	bcf	sda
	btfsc	flag,0
	bsf	sda
	bsf	scl
	CALL	dly_4uS
	bcf	scl
	bcf	sda
	CALL	dly_4uS
	retlw	0
Ack	bsf	scl
	CALL	dlv 4uS
	bcf	scl
	CALL	dly_4uS
	retlw	0

#### DacStart

bsf	sda
nop	
bsf	scl
CALL	dly_4uS
bcf	sda
CALL	dly_4uS
bcf	scl
retlw	0

#### DacStop

bsf	scl	
CALL	dly_4uS	
bsf	sda	
CALL	dly_4uS	
bcf	scl	
nop		;Delay 400nS each
bcf	sda	
retlw	0	

#### 

;4.4uS eelay routine

#### ; \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \* \*

dly\_4uS

movlw .2 ;

dlvloop4u	movwf	tempdl		;
al/100p10	nop decfsz goto	tempd1,1 dlyloop4uS	; ;	;
	return			;
;******				
;1 ms delay routine				
; * * * * * * * * * * * * * * * * *				
d10_1ms				
	movlw	. 4		;
	movwi			;
ατλ <sup>-</sup> τωλ	moutuf	.204 tompd2		΄.
dly 1my	deafaz	tempd2 1		'
diy_inx	goto	dly lmy	,	
	clrwdt	diy_imx		;
	decfsz	tempd1.1	;	·
	goto	dlv 1mv		;
	return			;
, 10 mg delaw routine				
;*******************				
d10 10ms				
	movlw	.32		;
	movwf	tempd1		;
dly_10y	movlw	.255		;
	movwf	tempd2		;
dly_10x	decfsz	tempd2,1	;	
	goto	dly_10x		;
	clrwdt			;
	decfsz	tempd1,1	;	
	goto	dly_10y		;
	return			;

end

# МICROCHIP MICROID™ 13.56 MHZ DESIGN GUIDE

## **Recommended Assembly Flows**



#### 2.0 WAFER ASSEMBLY FLOW



NOTES:

NOTES:

NOTES:



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Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro<sup>®</sup> 8-bit MCUs, KEELOQ<sup>®</sup> code hopping devices, Serial EEPROMs and microperipheral products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.

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